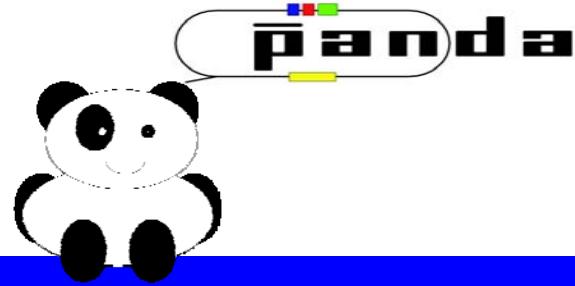


The silicon Micro Vertex Detector of the PANDA experiment



D. Calvo on behalf of the PANDA collaboration

12° Pisa Meeting on Advanced Detectors
La Biodola, Isola d'Elba, Italy, May 20-26, 2012



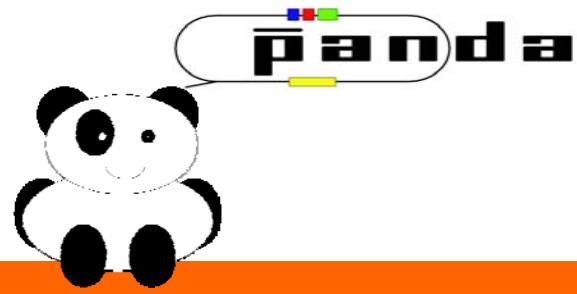
Overview

Introduction to the Micro Vertex Detector

- The layout optimization
 - Prototype results
 - Conclusions

D. Calvo



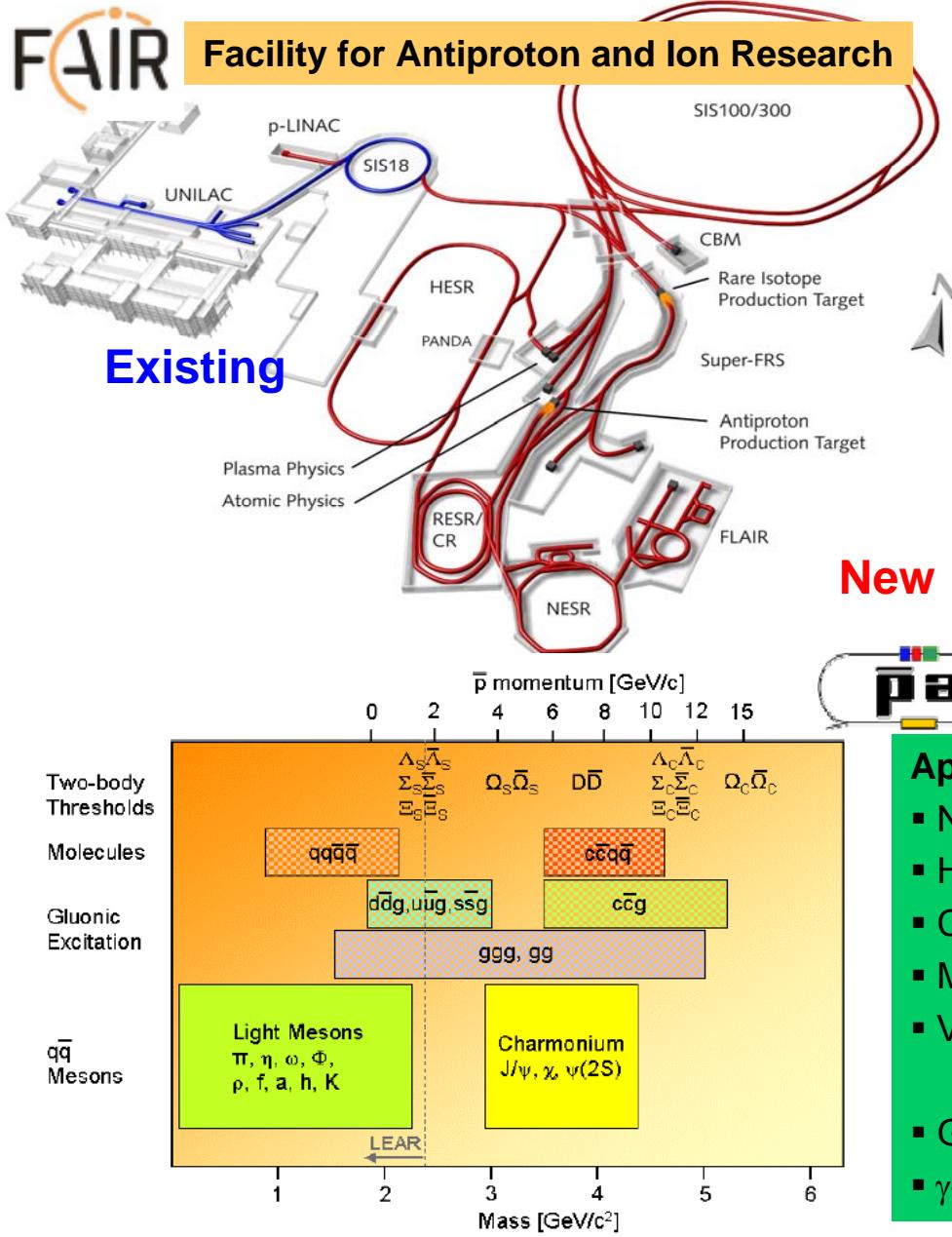


Introduction

D. Calvo

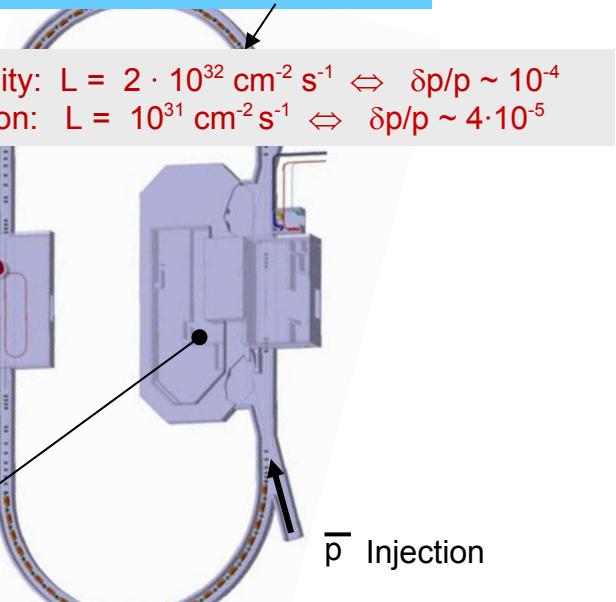


FAIR and PANDA



HESR – High Energy Storage Ring

High luminosity: $L = 2 \cdot 10^{32} \text{ cm}^{-2} \text{ s}^{-1} \Leftrightarrow \delta p/p \sim 10^{-4}$
 High resolution: $L = 10^{31} \text{ cm}^{-2} \text{ s}^{-1} \Leftrightarrow \delta p/p \sim 4 \cdot 10^{-5}$



Antiproton Annihilations at Darmstadt

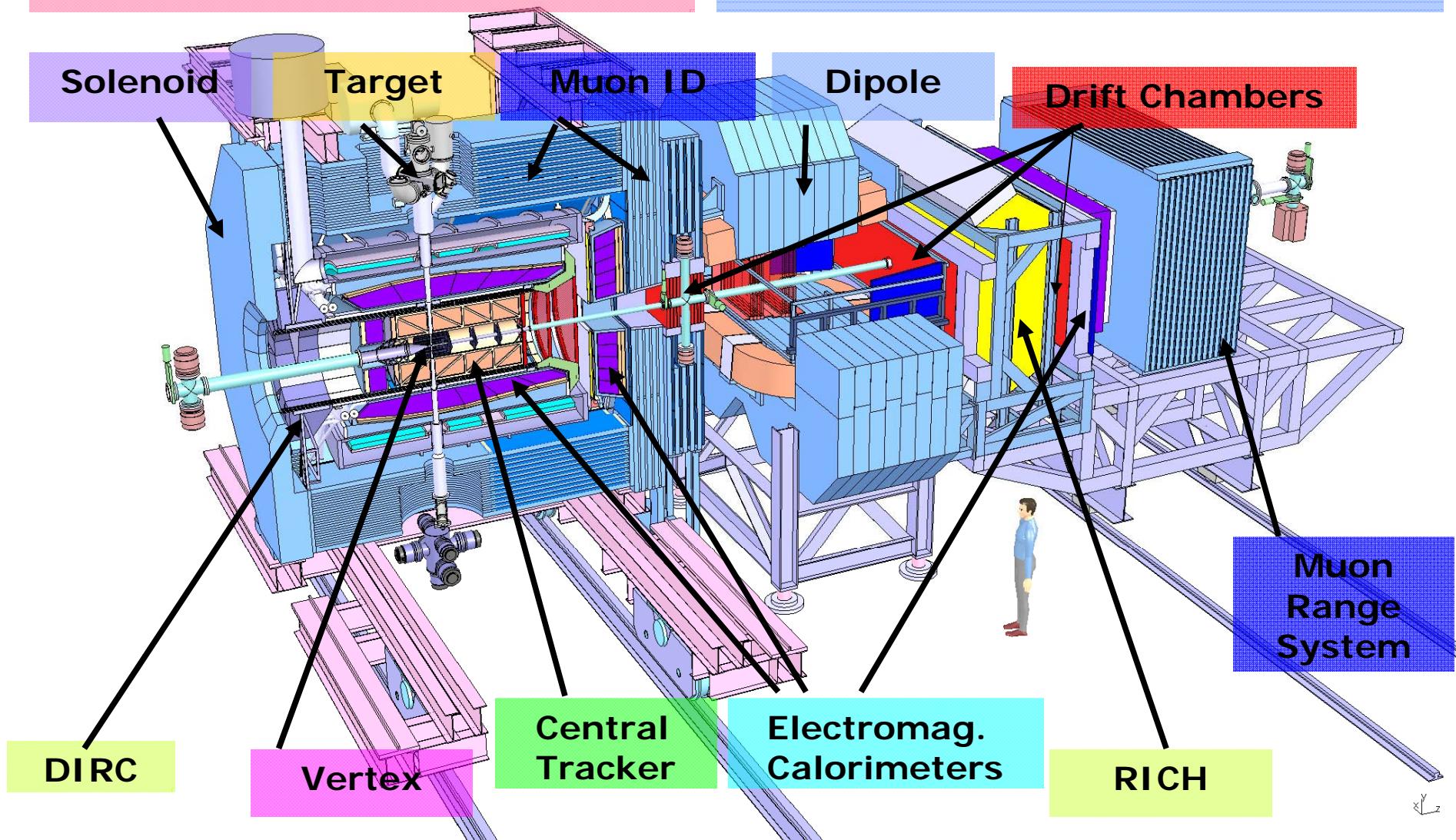
Apparatus requirements:

- Nearly 4π acceptance
- High rate capabilities ($2 \cdot 10^7 \text{ pbar-p annihilations /s}$)
- Continuous readout and efficient event selection
- Momentum resolution (1%)
- Vertex info for D, K^0_s, Λ ($c_\tau = 317 \mu\text{m}$ for D^+)
 - good tracking
- Good PID ($\gamma, e, \mu, \pi, k, p$) with Cherenkov, TOF, dE/dx
- γ -detection 1 MeV – 10 GeV with Crystal Calorimeter

PANDA

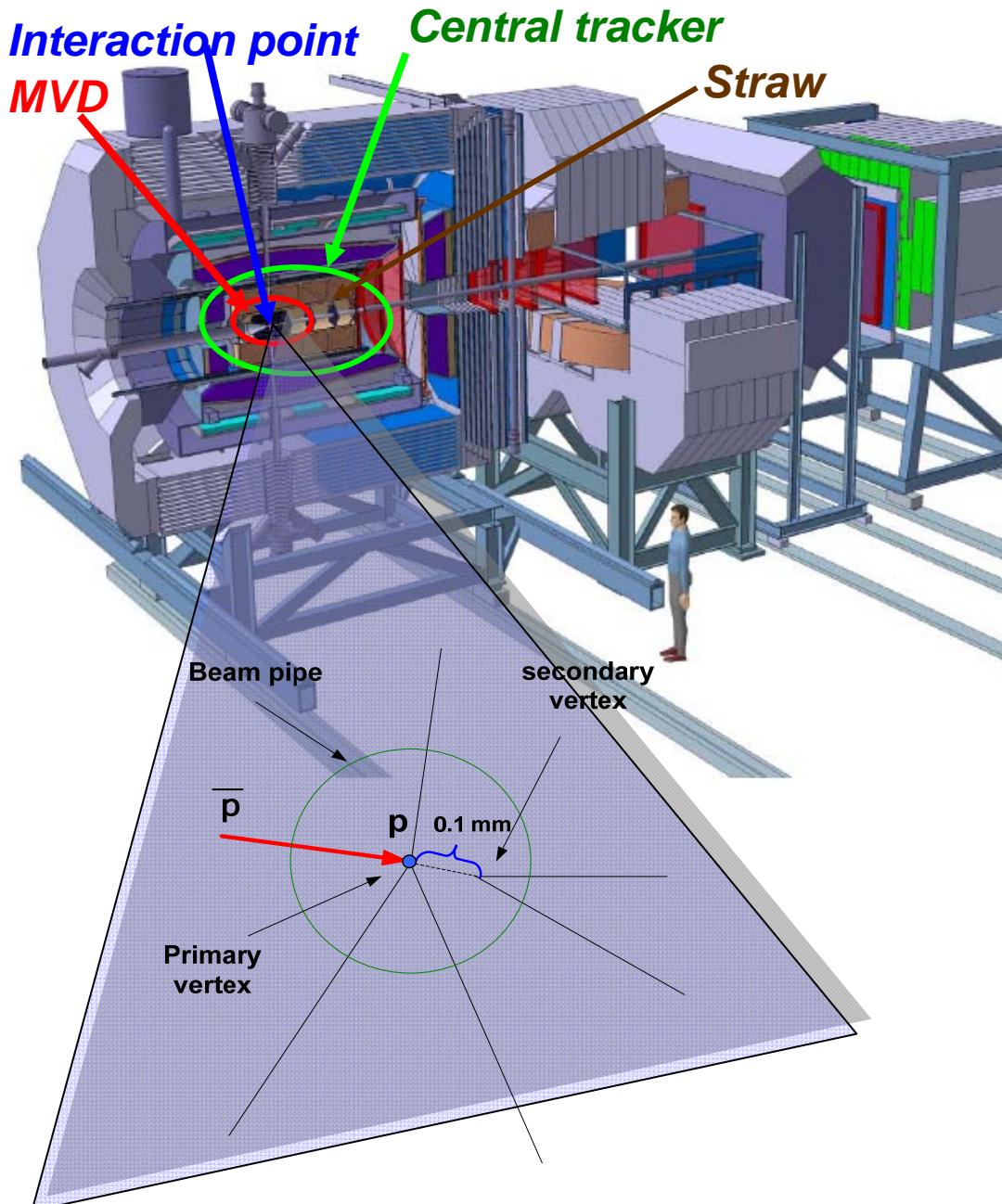
TARGET SPECTROMETER

FORWARD SPECTROMETER



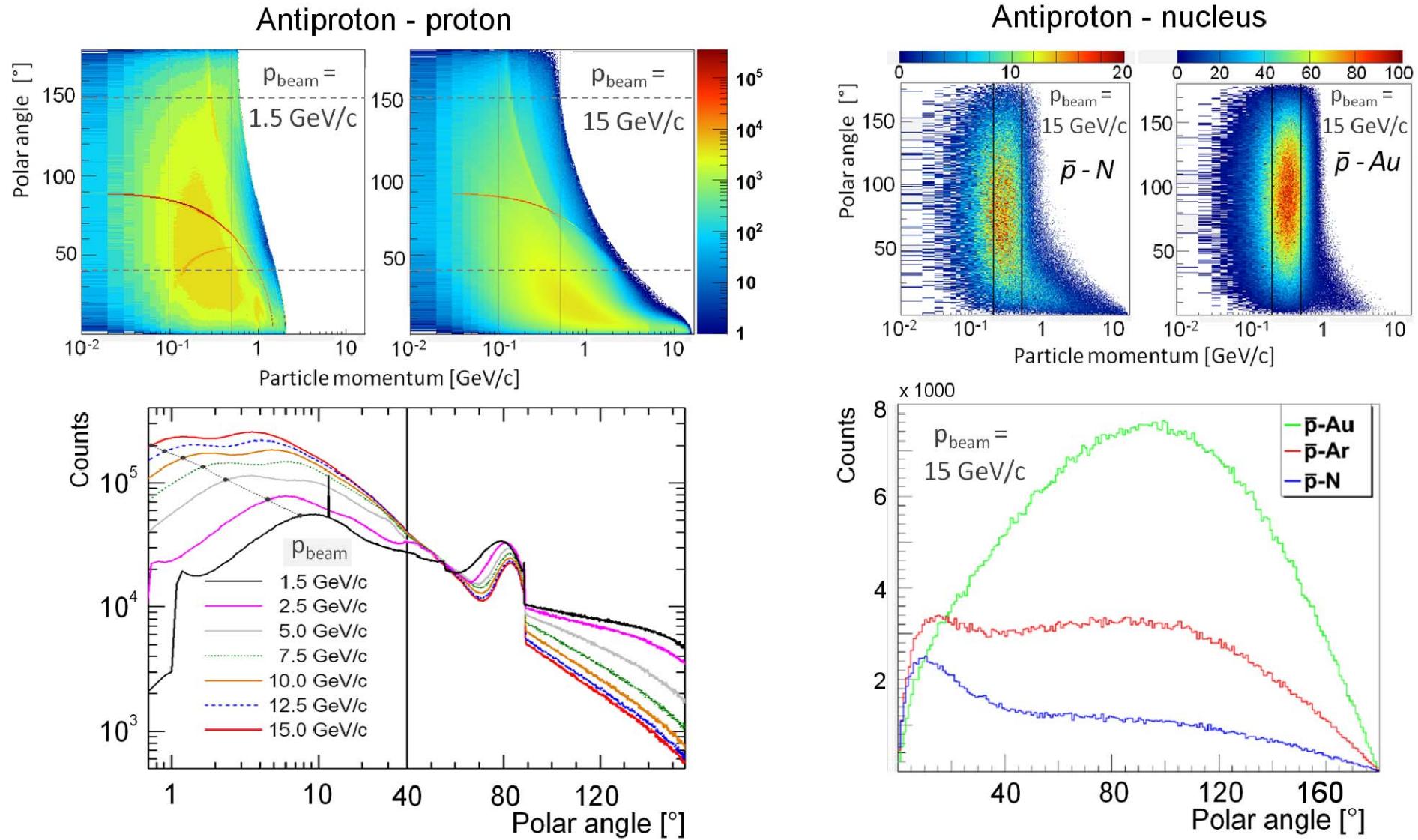
PANDA is a fixed target experiment with frozen hydrogen pellet and heavier nuclear targets (N, Ar...)

Towards the Micro Vertex Detector

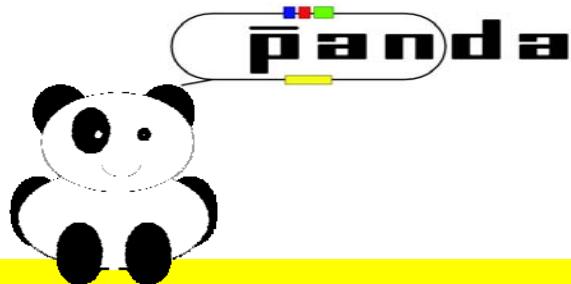


- Good spatial resolution in r-phi
 - Momentum measurement of soft pions from D^* decays
- Good spatial resolution especially in z
 - Vertexing, D-tagging
- Good time resolution
 - $O(20\text{ns})$ with $2 \cdot 10^7 \text{ ann/s}$
- Triggerless readout (155.52 MHz clock)
- Energy loss measurement
 - dE/dx for PID
- Low material budget
 - low momentum of particles (from some hundreds of MeV/c) ($<1\% X_0$ for each layer)
- Radiation hardness ($O(10^{14} n_{1\text{MeV eq}}/\text{cm}^2)$)
 - Depends on target
 - Different radiation load

Towards the Micro Vertex Detector



Particle distribution with enhanced emission in forward direction (light target)
and low-energetic particles ($< 1 \text{ GeV}/c$) in full polar angle



Micro Vertex Detector



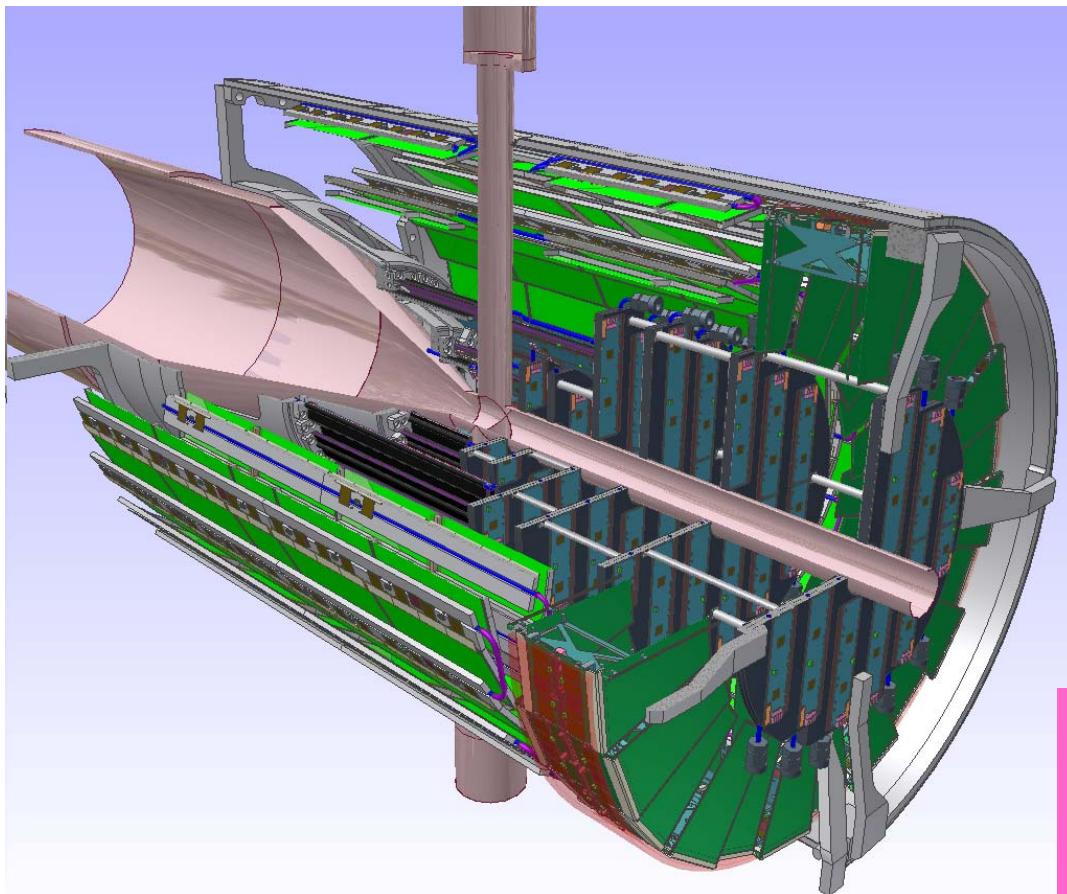
Fachhochschule
Südwestfalen



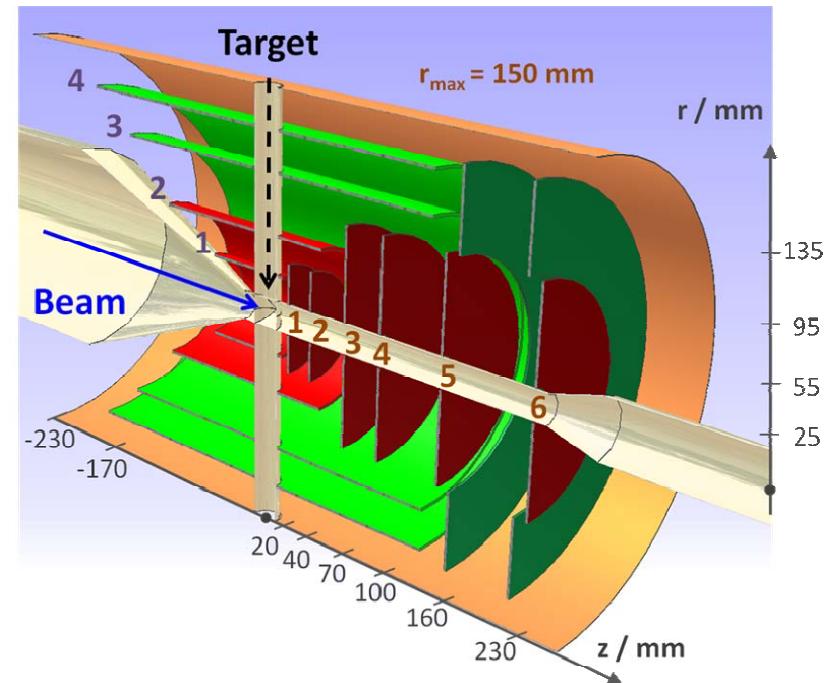
D. Calvo



MVD layout



Readout channels:
~ 11 million (pixel)
~ 200.000 (strip)

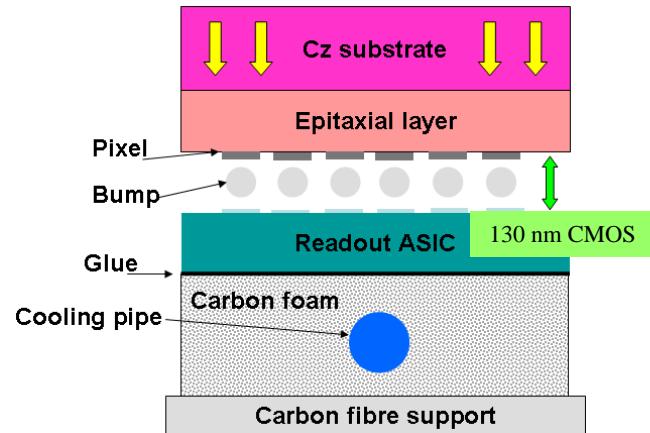


4 barrels
Two inner layers:
hybrid pixel detectors
Two outer layers:
double side silicon strip detectors

and **6 forward disks**
Four disks:
hybrid pixel detectors
Then two disks:
Mixed pixel and strips

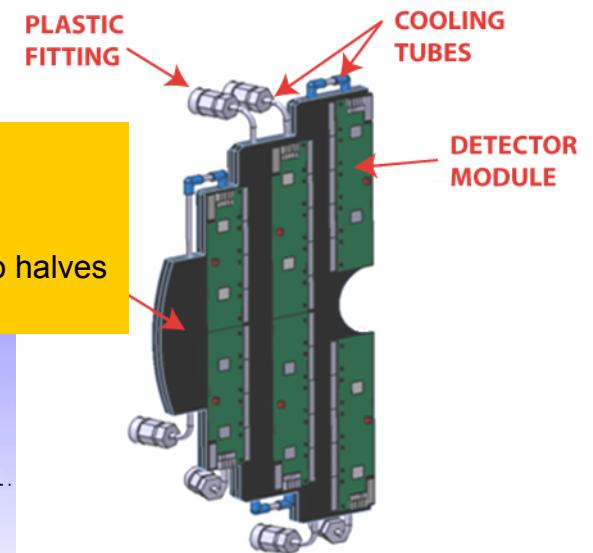
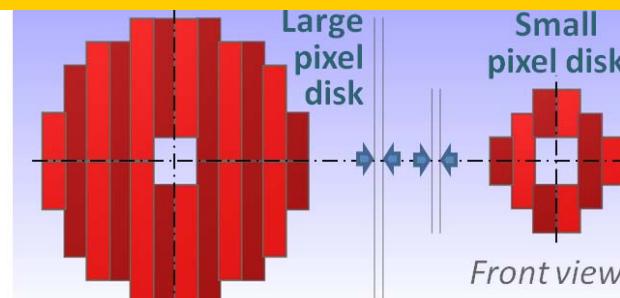
Hybrid pixel detector

Standard hybrid technology

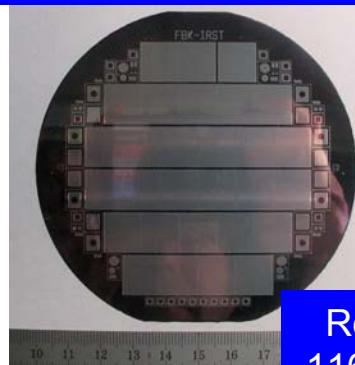


Pixel disk layout

- Disk split in two halves along the mid-plane
- Material for heat dissipation:
foam POCO-HTC
- Embedded cooling capillary between the two halves
- All elements glued with thermal glue

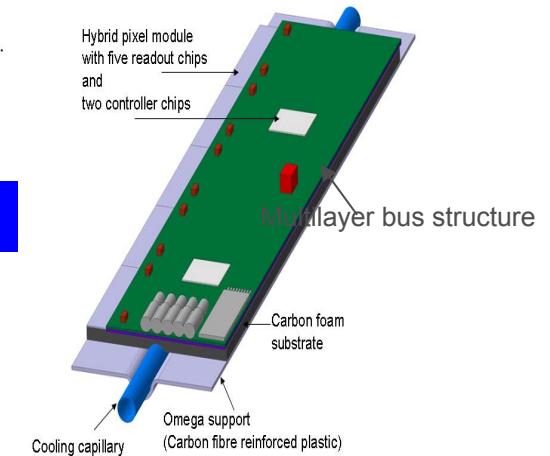
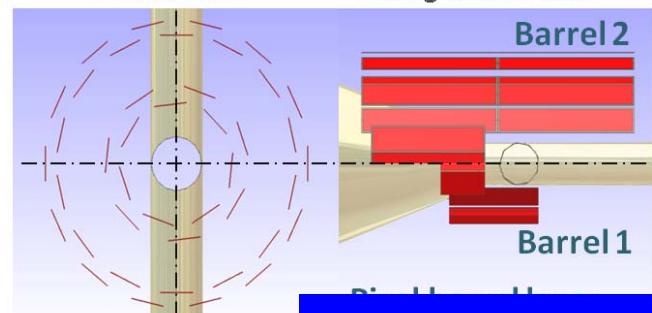


Pixel sensor size
Pixel cell size $100 \times 100 \mu\text{m}^2$
 $100 \mu\text{m}$ thickness

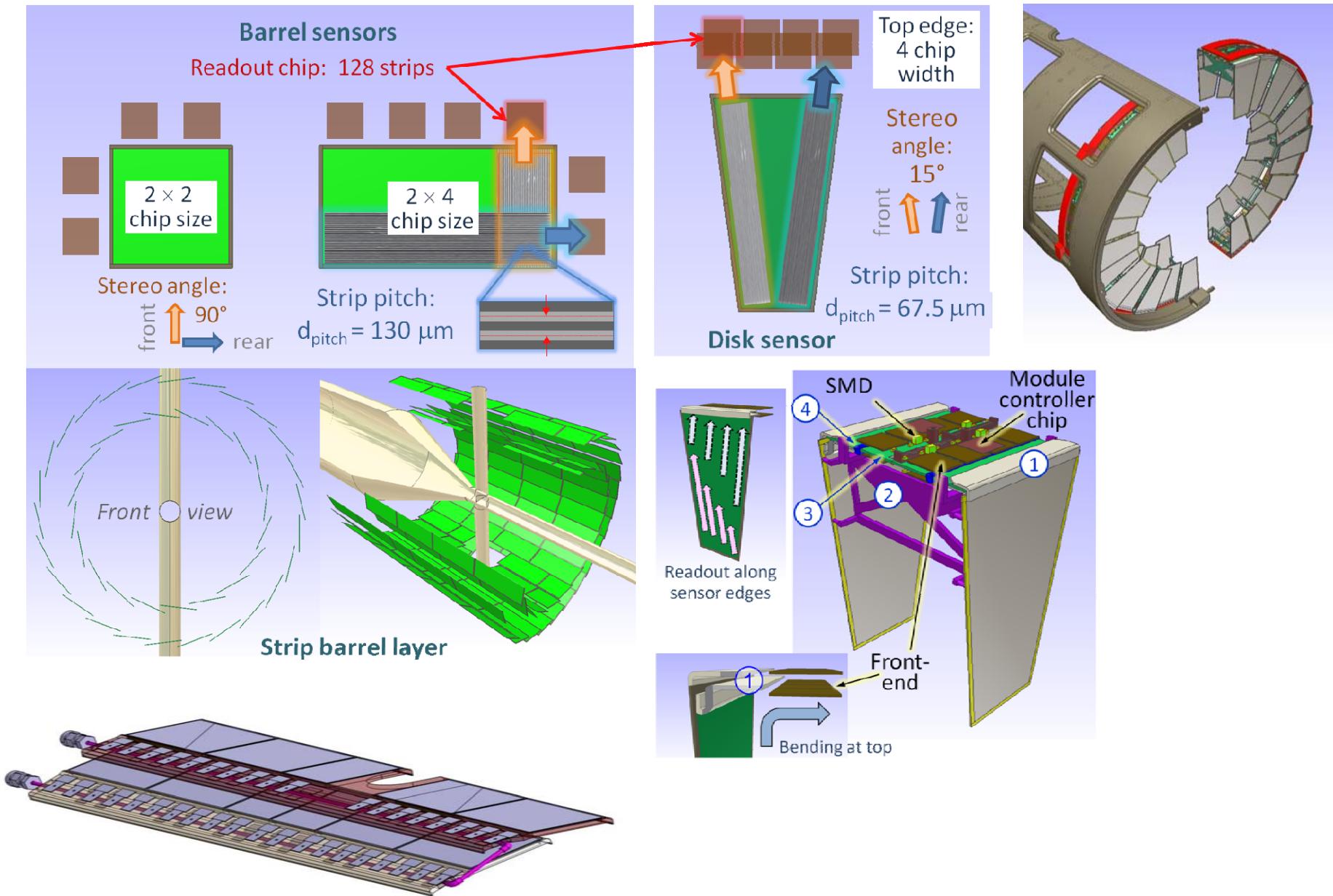


Readout chip:
116 x 110 pixels

Pixel barrel layout

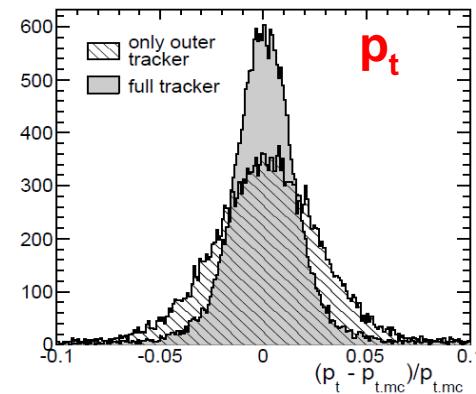
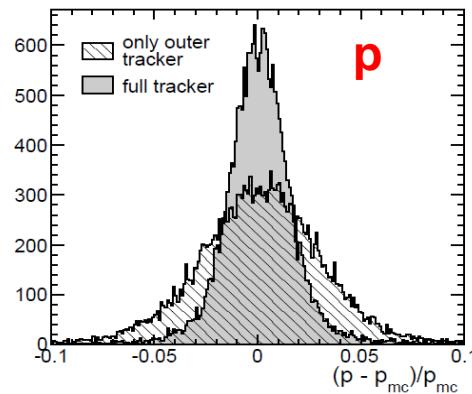


Double side silicon strips



Performance I

Momentum resolution



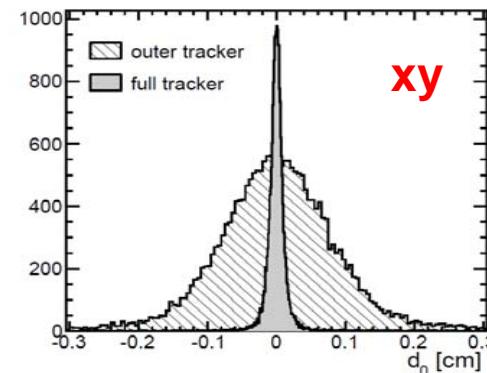
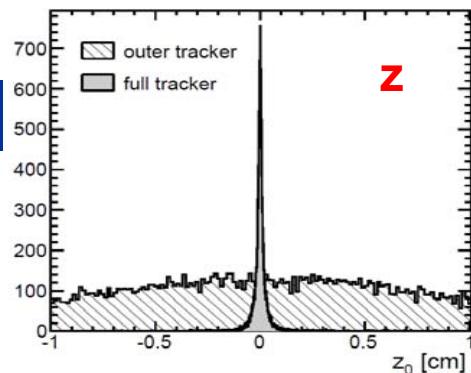
$\sigma(p)$ without MVD = 2.6 %
 $\sigma(p)$ with MVD = 1.4 %

$\sigma(p_t)$ without MVD = 2.9 %
 $\sigma(p_t)$ with MVD = 1.4 %

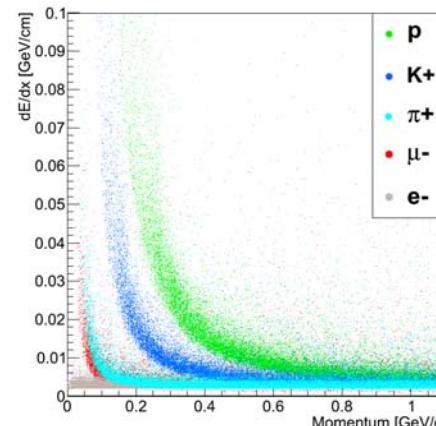
→ Improvement by 50%

Single track resolution

→ No resolution along z without MVD



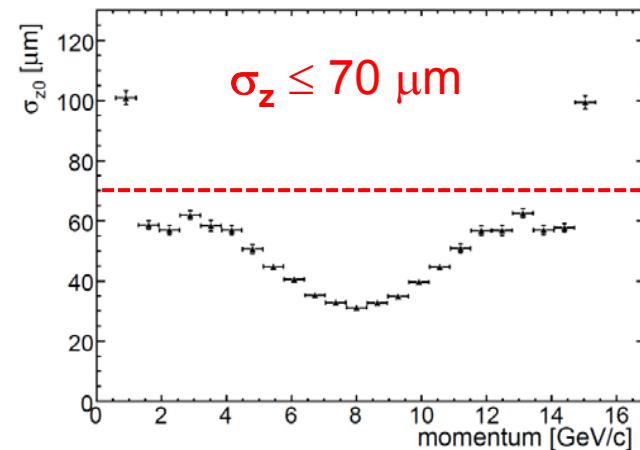
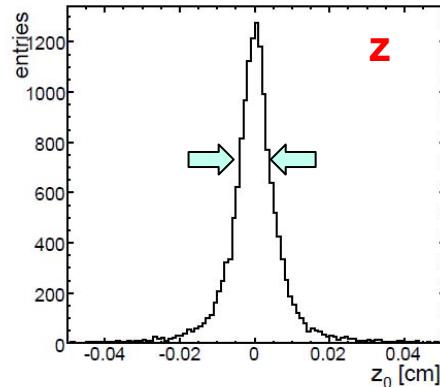
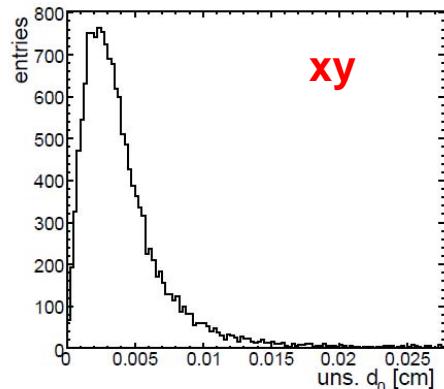
Energy loss information



Performance II

Primary vertex resolution

$\bar{p}p \rightarrow \pi^+ \pi^-$ 15 GeV/c



Vertex resolution

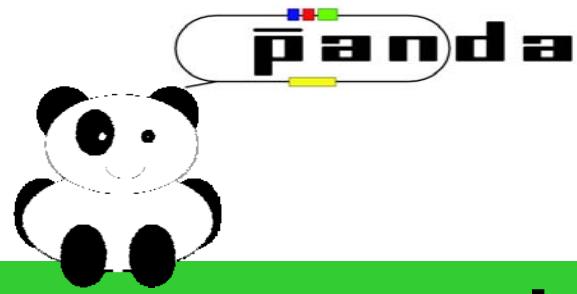
$\bar{p}p \rightarrow D^+ D^-$ (6.57 / 7.50 / 8.50) GeV/c

momentum GeV/c	vertex resolution [μm]					
	primary			secondary		
	$\sigma_{prim,x}$	$\sigma_{prim,y}$	$\sigma_{prim,z}$	$\sigma_{sec,x}$	$\sigma_{sec,y}$	$\sigma_{sec,z}$
6.57	30.7	30.7	493.6	35.4	35.2	77.1
7.50	30.4	30.3	208.5	37.1	36.4	84.0
8.50	30.0	29.0	157.4	36.7	36.2	92.4

→ Secondary
vertex resolution:

$$\sigma_{x,y} \leq 35 \text{ } \mu\text{m}$$

$$\sigma_z \leq 100 \text{ } \mu\text{m}$$

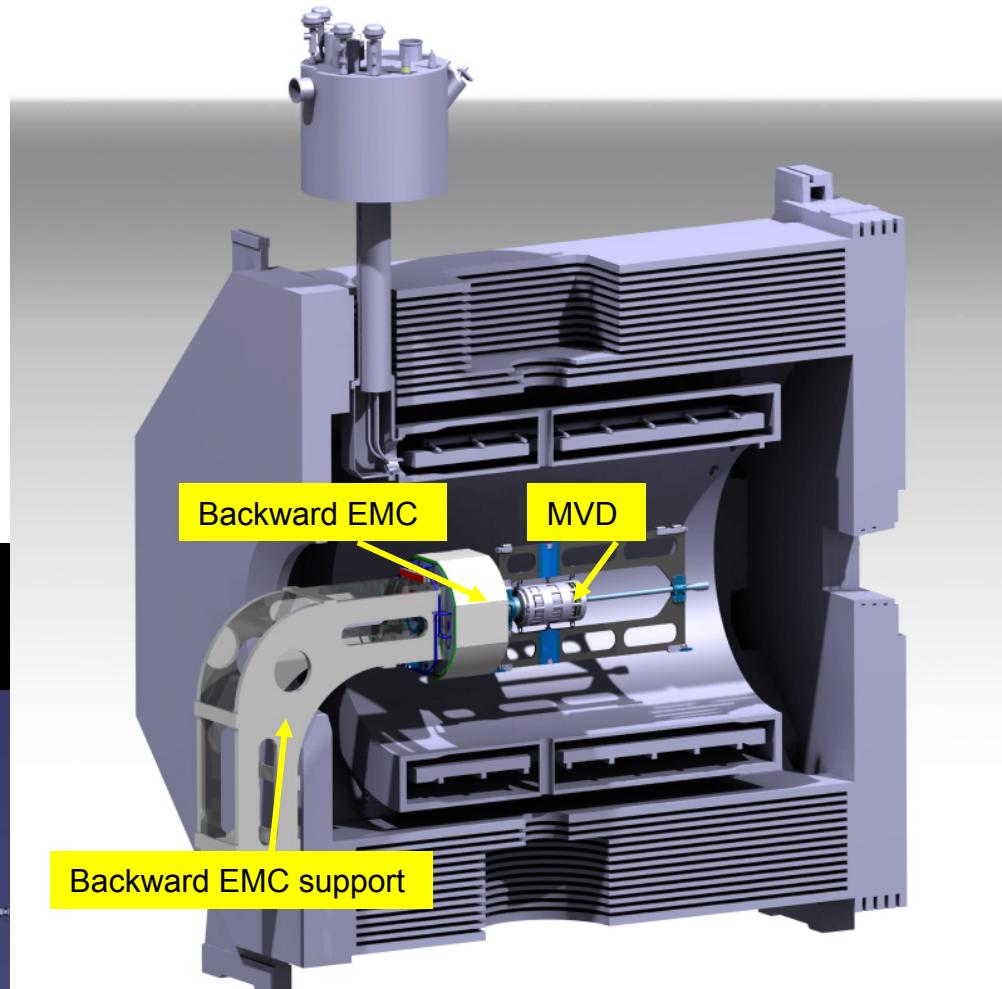
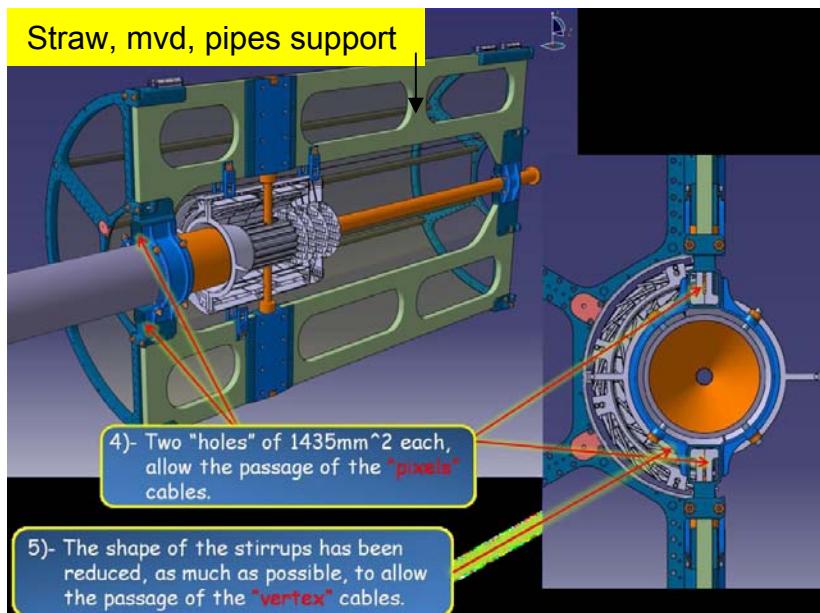
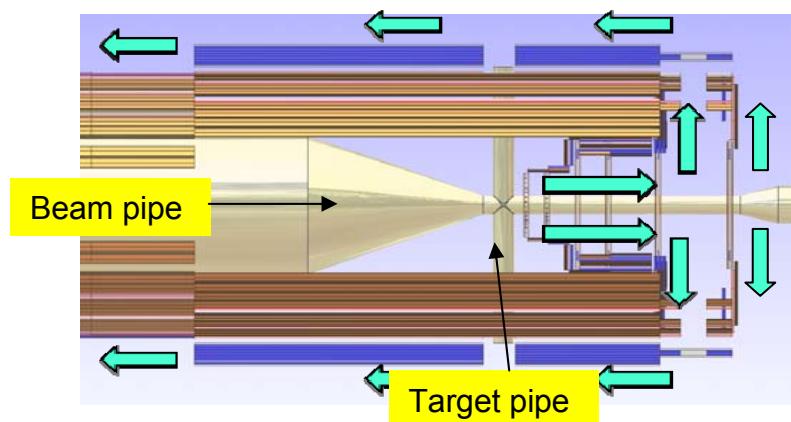


Layout optimization

D. Calvo



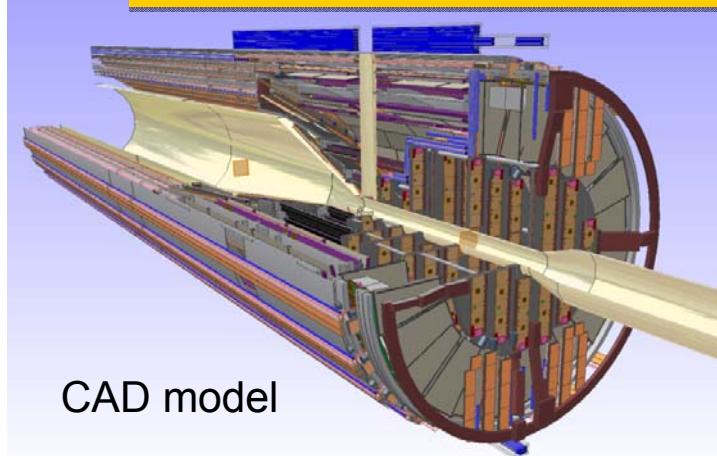
Layout and routing scheme



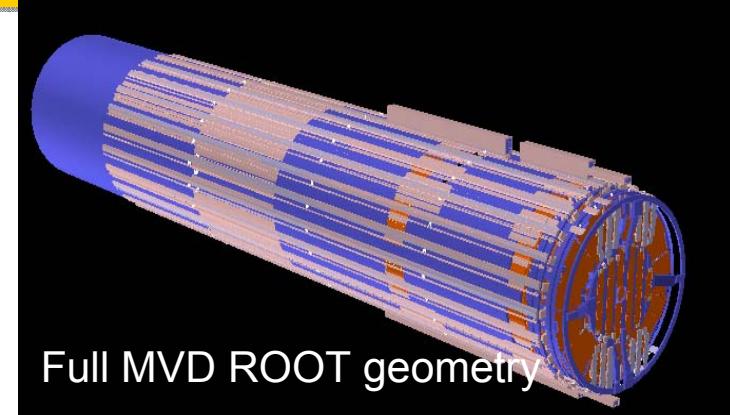
CAD converter → simulations

CAD Converter

translates CAD drawings (STEP-files) into ROOT geometries → access to full pandaROOT simulation with realistic detector design

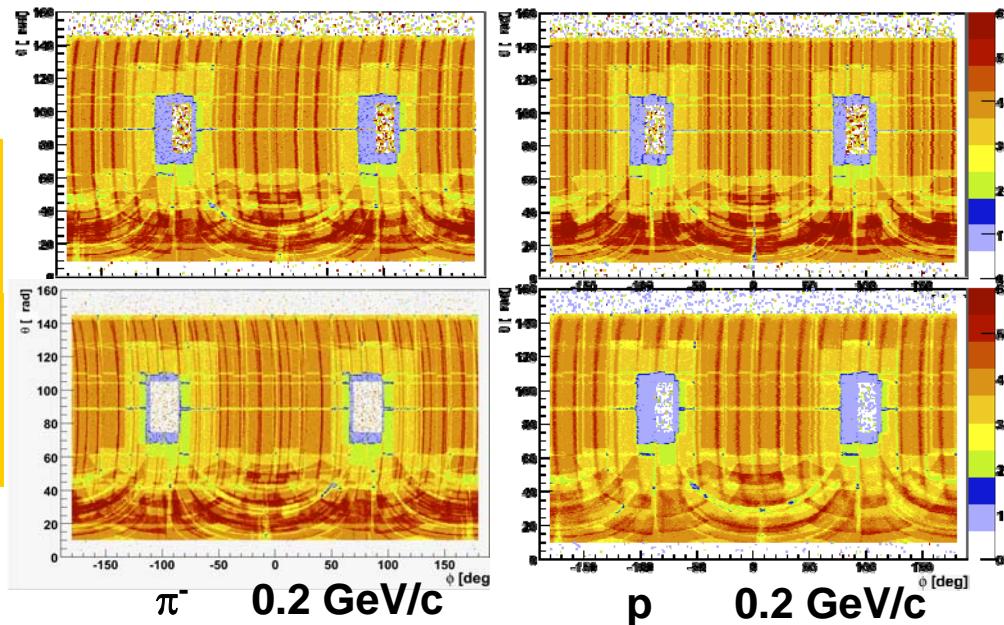


CAD model



Full MVD ROOT geometry

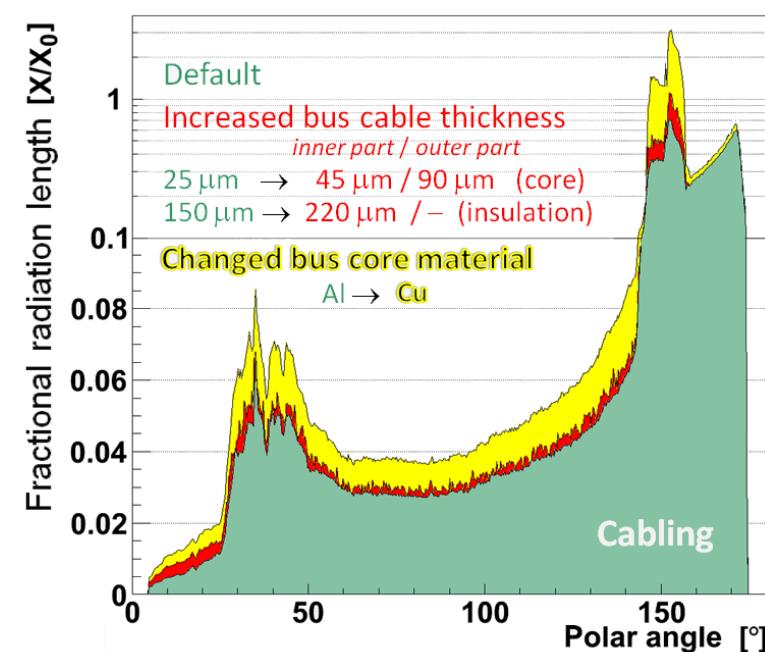
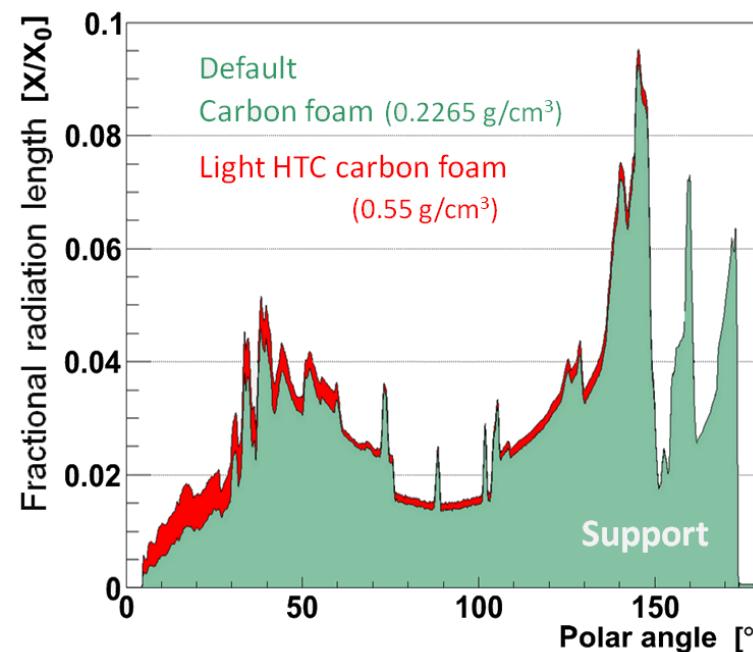
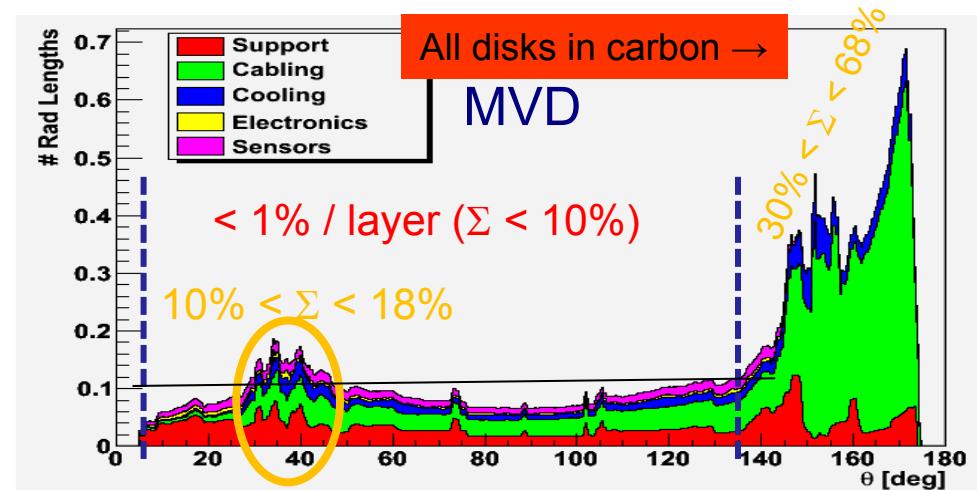
$\pi^+ 0.2 \text{ GeV}/c \rightarrow 1.5 \text{ GeV}/c$



Spatial coverage

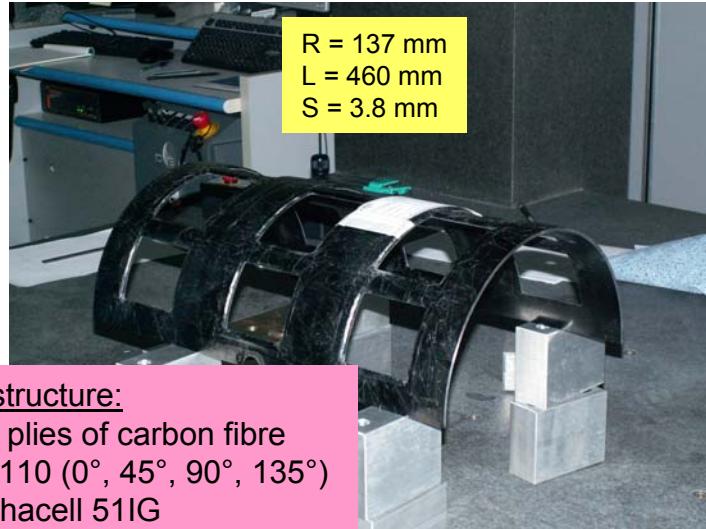
- 2D mapping: Number of MVD points / track
- Design optimization for a minimum of 4 track points
- No significant effect for particle-antiparticle
- No significant energy dependence
- No significant effect for different particle species

Radiation length studies



Light mechanical structures and cooling

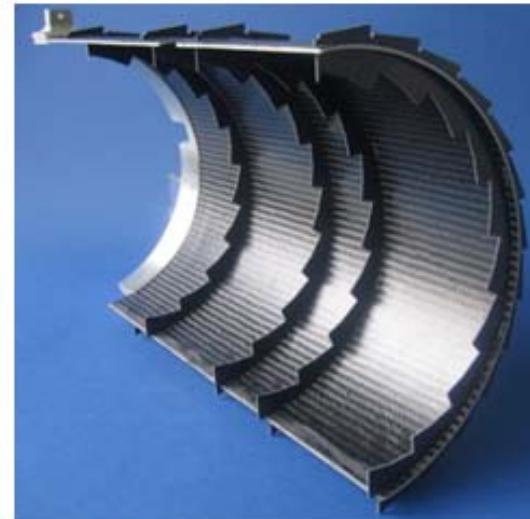
MVD half support frame



sandwich structure:

2 skin → 4 plies of carbon fibre
M55J/LTM110 (0°, 45°, 90°, 135°)
core → Rohacell 51IG
Radiation Length $X_0 \approx 0,4\%$

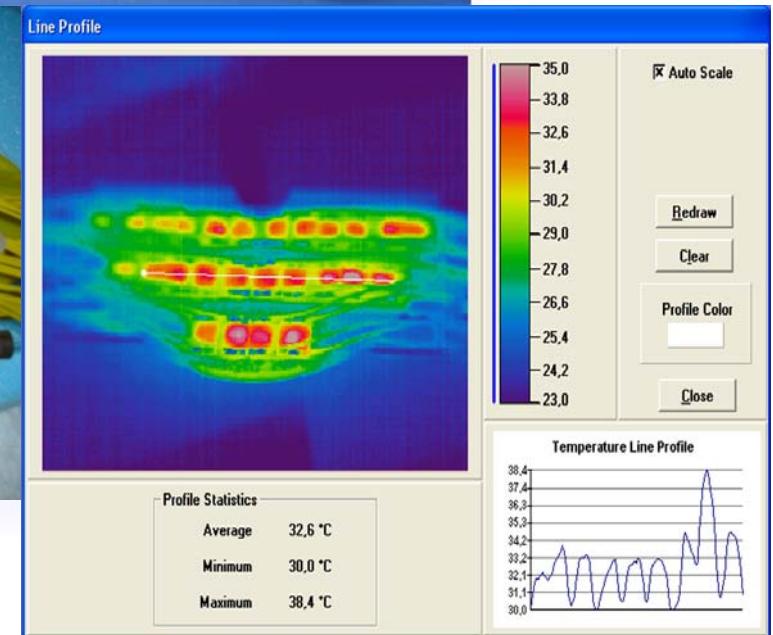
Strip barrel support
Cylinder over full length



- Total Power 94 W (1,75 W each dummy chip).
- Cooling pipe diameter 2 mm (MPN35N Ni-Co alloy),
- 4 mm carbon foam
- Cooling flow 0,3 lit/min
- Htc therm. conductivity = 50 W/m·K



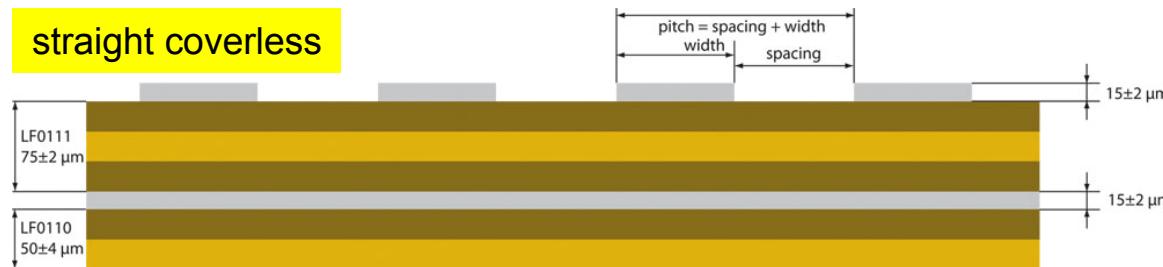
HTC foam pixel half disk



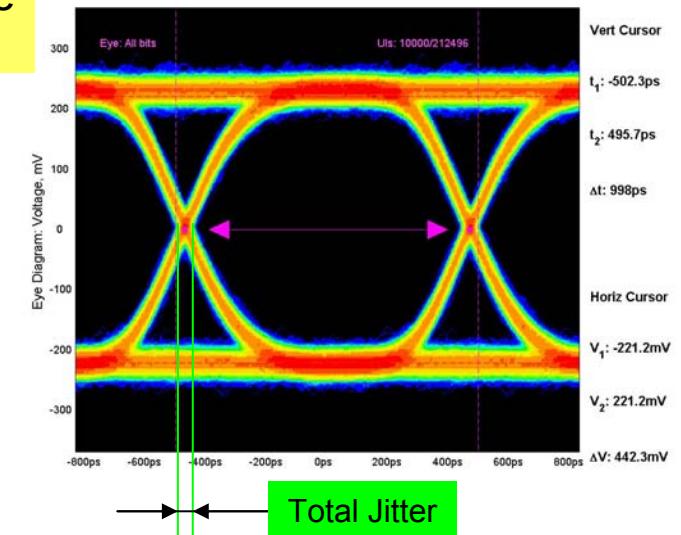
1 m long aluminum strips prototypes

Technology based on laminated aluminum on kapton, reliable for bonding, produced @ CERN according to our design

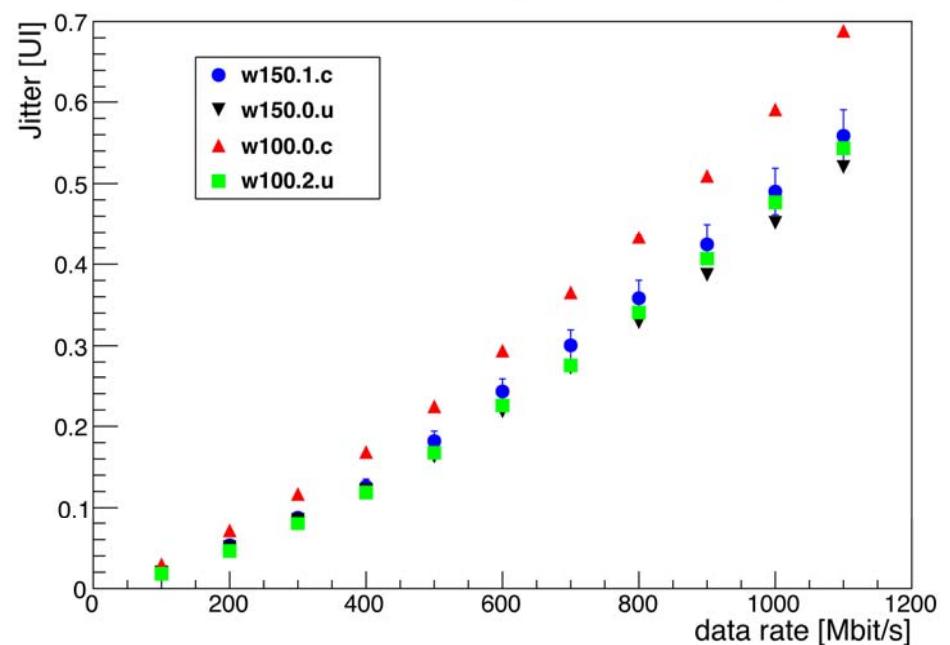
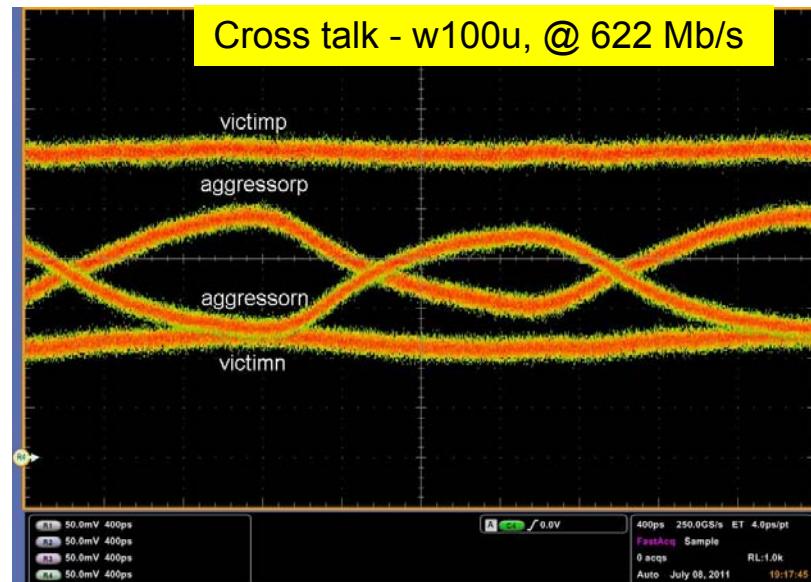
straight coverless



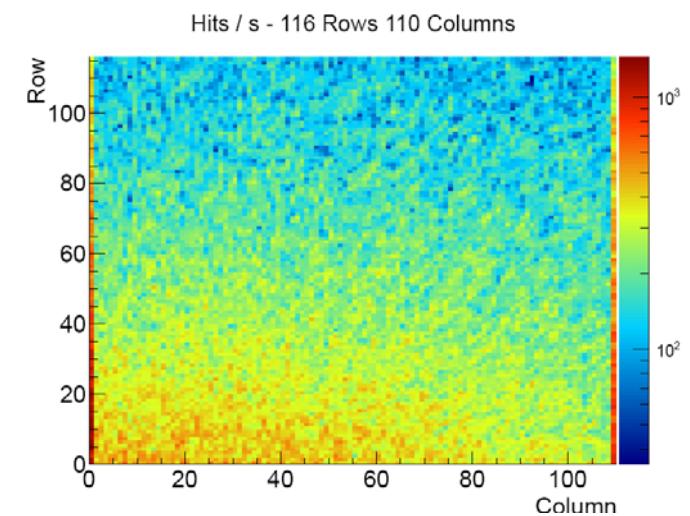
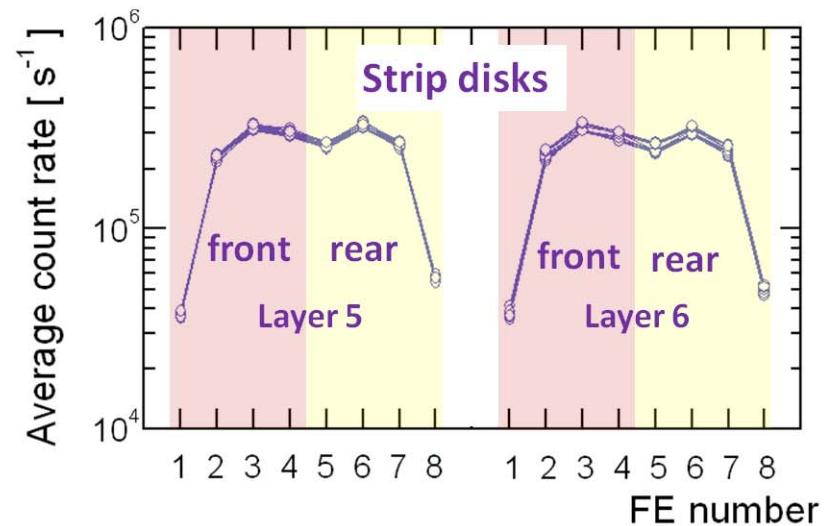
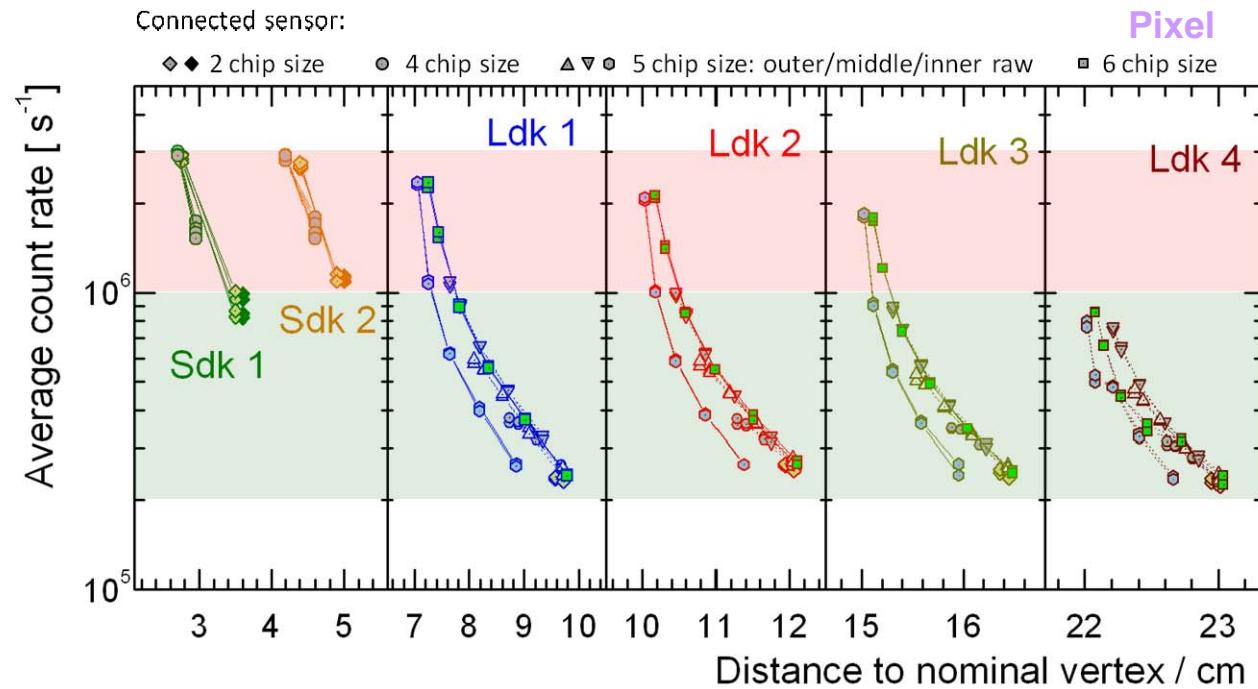
18 differential pairs



Jitter vs Data Rate (cable only, SLVS)

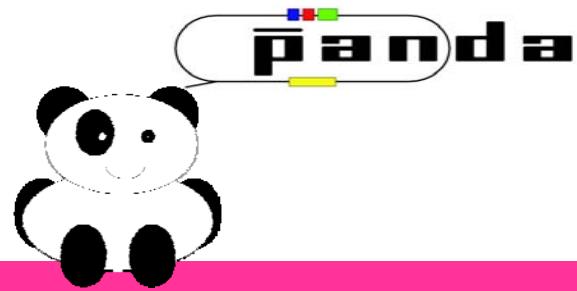


Data Rate



Data load from MVD (@ $2 \cdot 10^7$ ann/s) ~ 38 Gb/s

Map of the hits on the hottest pixel readout
(@ $2 \cdot 10^7$ events)



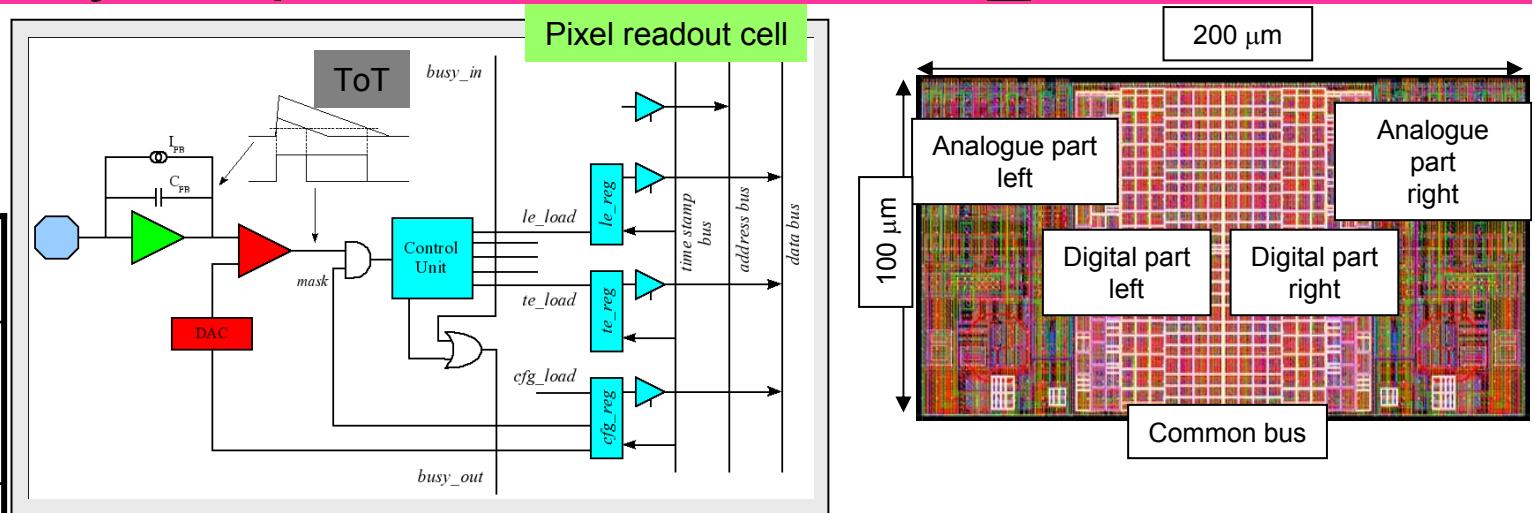
Prototypes

D. Calvo

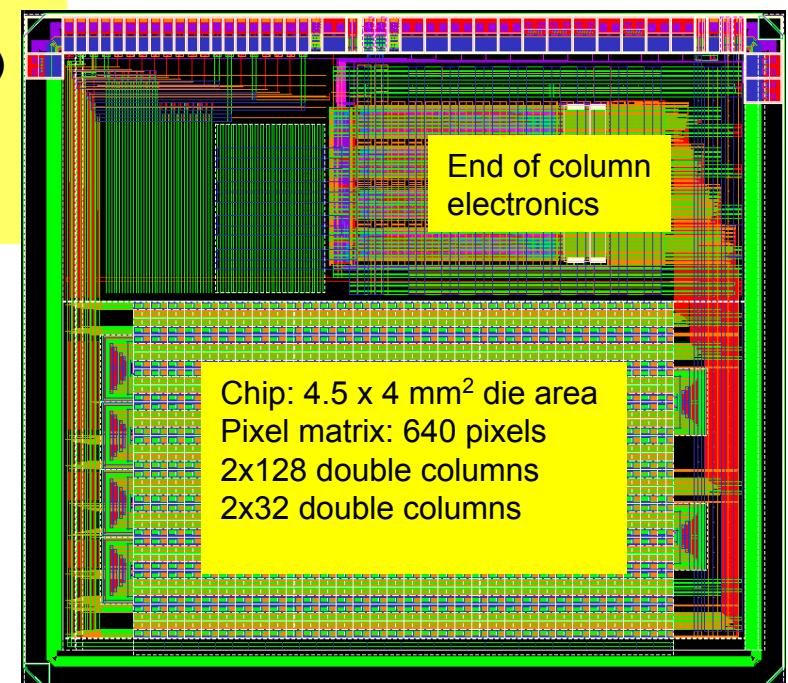


Hybrid pixel detector I: ToPix_v3

ToPix Specifications - 130nm CMOS technology	
Pixel readout size:	100 x 100 μm^2
Chip active area:	11.4 x 11.6 mm^2 (116 rows, 110 columns)
dE/dx measurement:	ToT, 12 bits dynamic range (max. Input charge: 50 fC)
Noise:	< 0.032 fC (200 e ⁻)
Clock frequency:	155.52 MHz
Time resolution:	6.4 ns (1.85 ns rms)
Power consumption:	< 750 mW/cm ²
Total ionizing dose:	< 100 kGy
Max.event rate:	(at 2 10^7 pbar-p ann/s): $\sim 3 \cdot 10^6$ hits/ (chip · s)



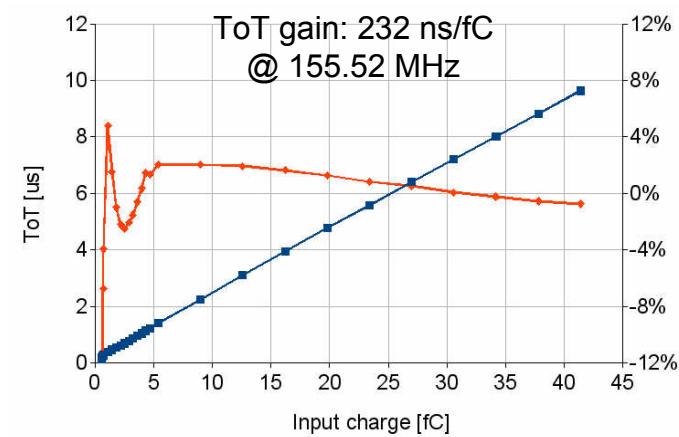
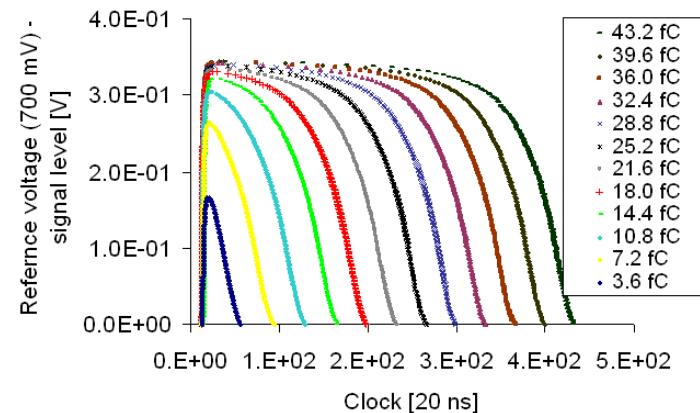
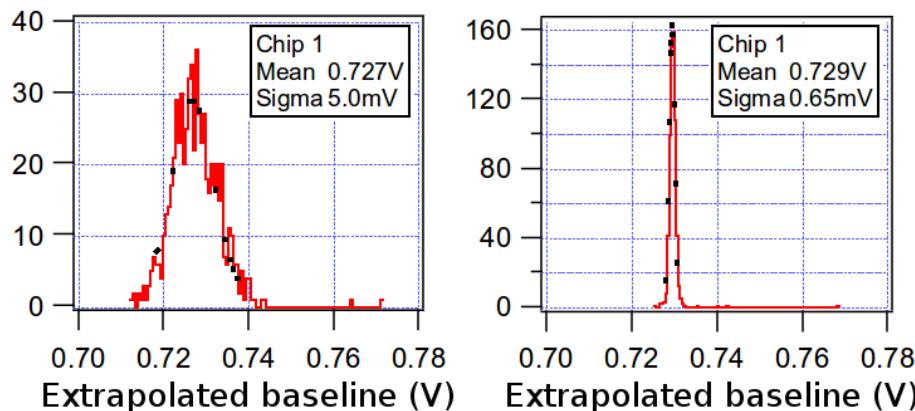
CMOS 130 nm DM technology
Triggerless
Triple redundancy-based SEU protection (cell)
Hamming encoding (EoC)
Serial output (e-link compatible) and SLVS I/O
Pads for bump bonding



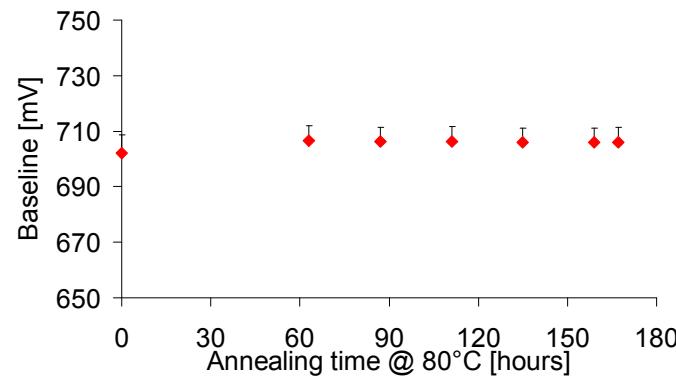
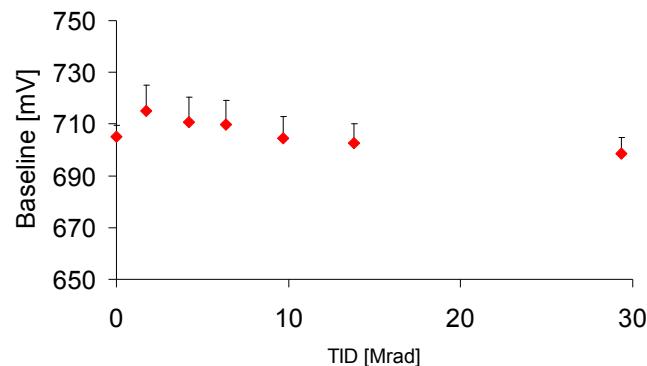
Hybrid pixel detector II: ToPix_v3

ToPix_v3 prototype – electrical functionalities

→ The pixel Detector readout ASIC for the Micro Vertex Detector of the PANDA experiment, G. Mazza et al.
 (Front End, trigger, ...**Poster Session**)



Total Ionizing Dose (400 rad/s @CERN)



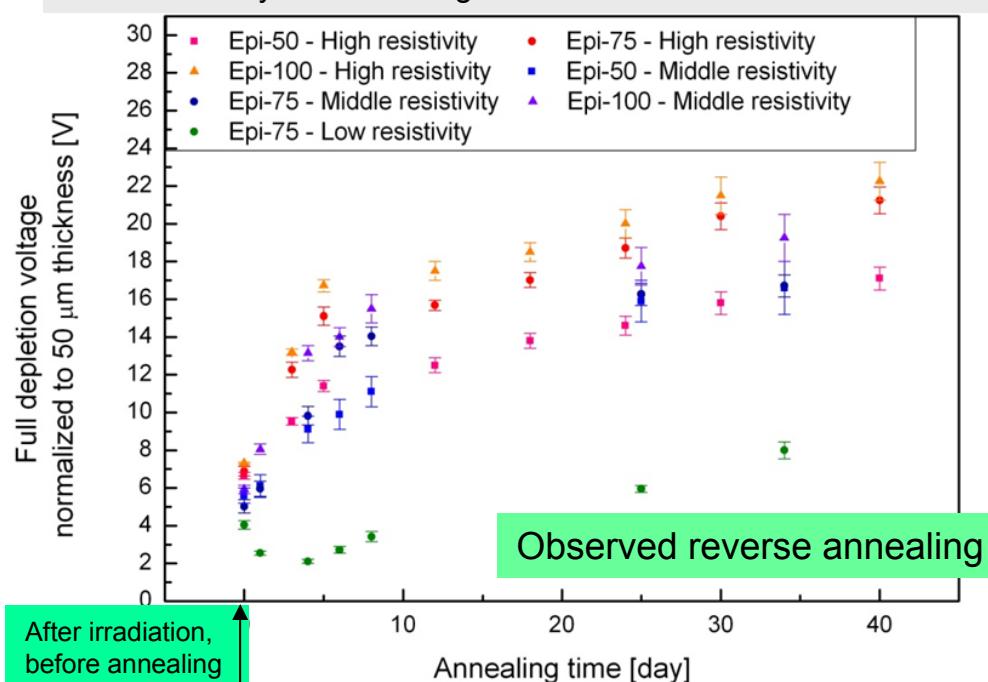
Hybrid pixel detector III: sensor prototypes

Test of radiation damage with neutrons from Pavia nuclear reactor up to 1.5 ± 10^{14} 1 MeV equivalent neutron/cm² corresponding to ~ 10 years of PANDA lifetime (DPM 15 GeV/c-NIEL)

Epi-50, HR: 49 μm (4060 $\Omega\cdot\text{cm}$, n/P)
Epi-75, HR: 74 μm (4570 $\Omega\cdot\text{cm}$, n/P)
Epi-100, HR: 98 μm (4900 $\Omega\cdot\text{cm}$, n/P)
Epi-50, MR: 50 μm (3100 $\Omega\cdot\text{cm}$, n/P)
Epi-75, MR: 75 μm (3200 $\Omega\cdot\text{cm}$, n/P)
Epi-100, MR: 100 μm (3610 $\Omega\cdot\text{cm}$, n/P)
Epi-75, LR: 75 μm (3610 $\Omega\cdot\text{cm}$, n/P)
+ Cz substrate (0.01-0.02 $\Omega\cdot\text{cm}$, n+/Sb)

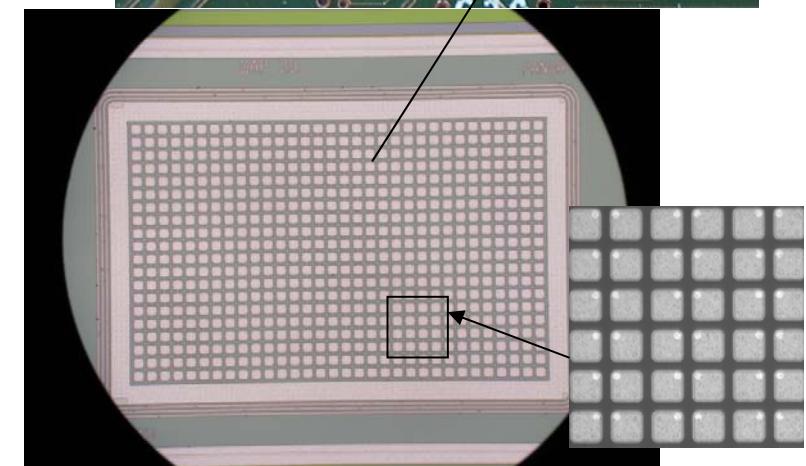
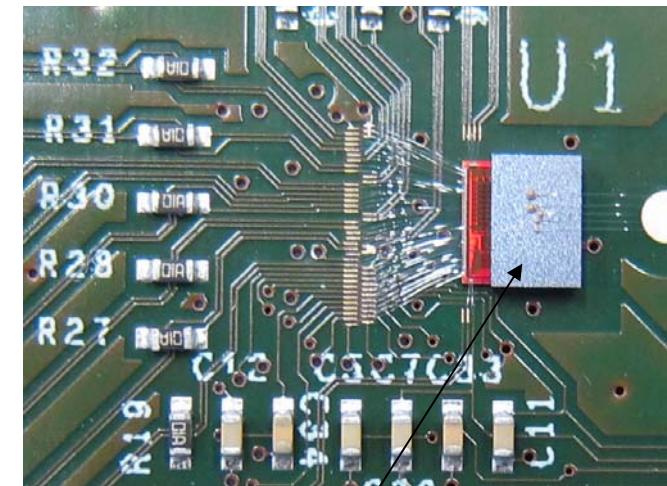
Diodes

Leakage current < 20 nA/pixel (100 $\mu\text{m} \times 100\mu\text{m}$ size, 100 μm thick), immediately after the irradiation. It decreases by a factor 2 after some days of annealing at 60°C



Single chip assembly

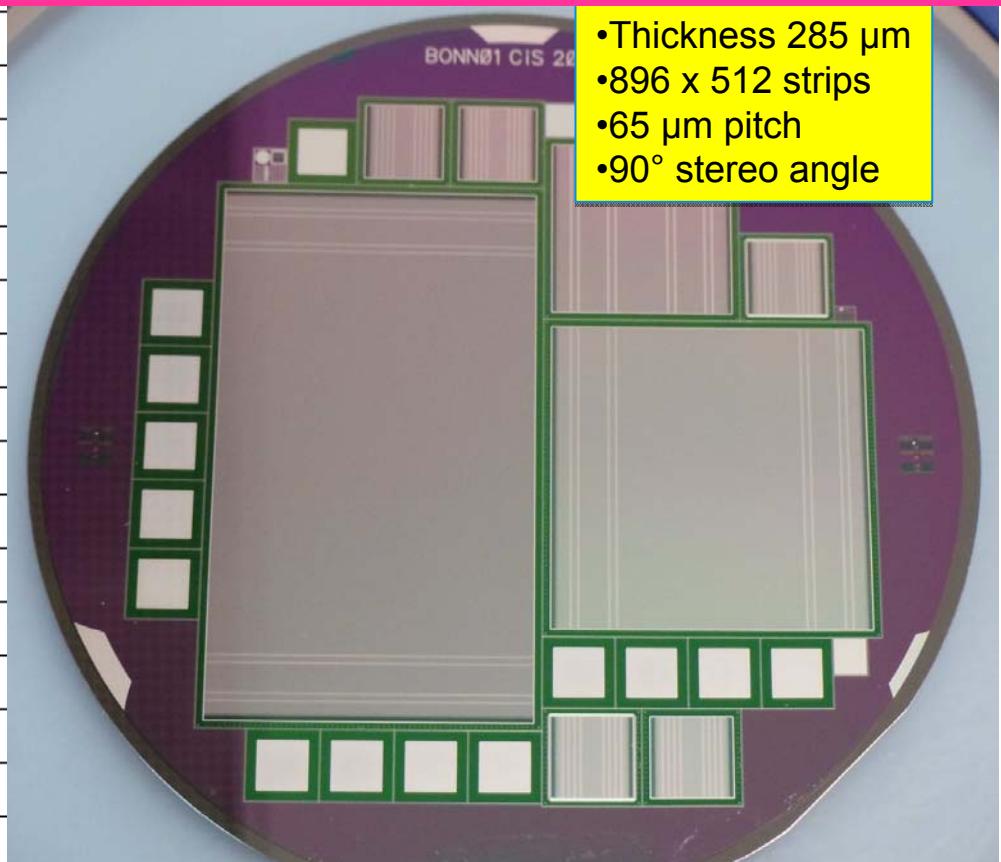
- ✓ pixel obtained with Epi-100, MR: 100 μm (3610 $\Omega\cdot\text{cm}$, n/P)
- ✓ Readout with ToPix_v3



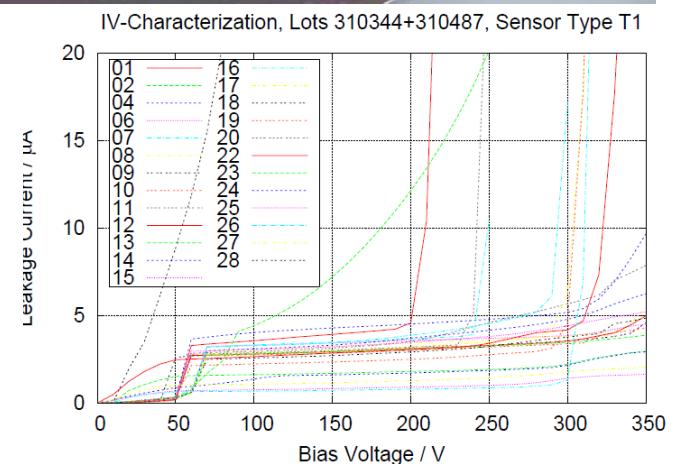
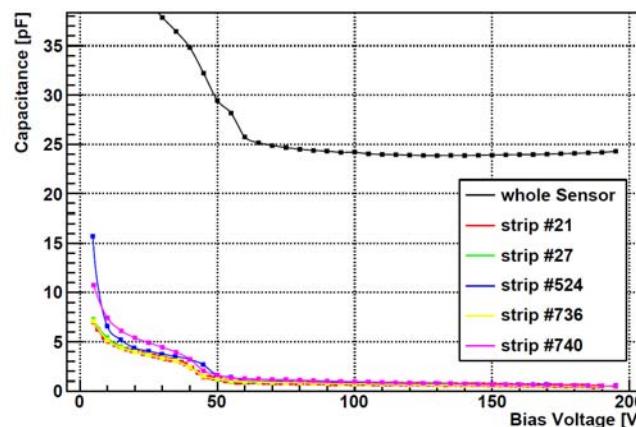
→ Development of thin pixel detectors on epitaxial silicon for HEP experiments, M. Boscardin et al.
(Solid State Detectors Poster Session)

Strip detector

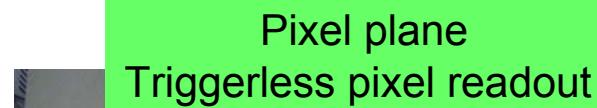
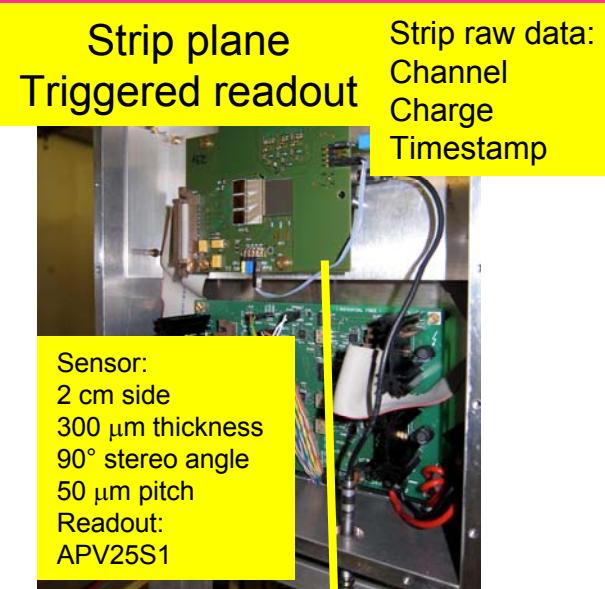
Parameter	adapted ToPix
input pad pitch	$\approx 50 \mu\text{m}$
channels per front-end	128
dynamical range	100 fC
ENC	1,000 e ⁻ @ 20 pF
peaking time	6 ns
power consumption	0.8 mW/ch
trigger	self-triggering
digitisation technique	ToT
digitisation resolution	10 bit
time resolution	1.85 ns @ 155 MHz
data interface	e-link - SLVS
number of data lines	1 pair
slow control	custom (serial)
process	0.13 μm CMOS
radiation hardness	10 MRad



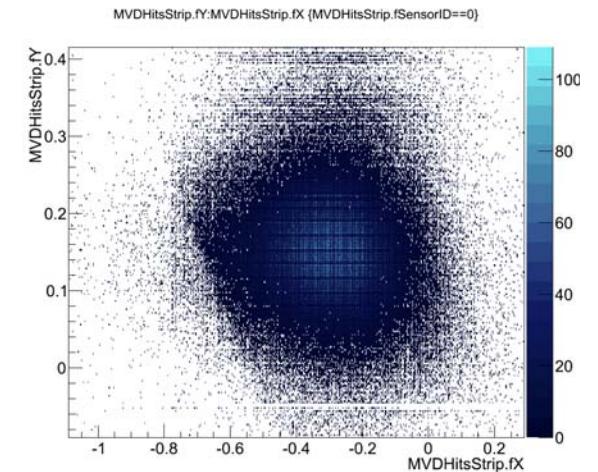
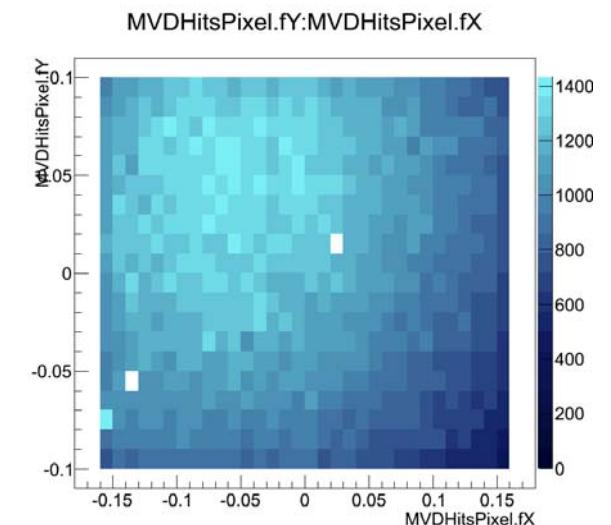
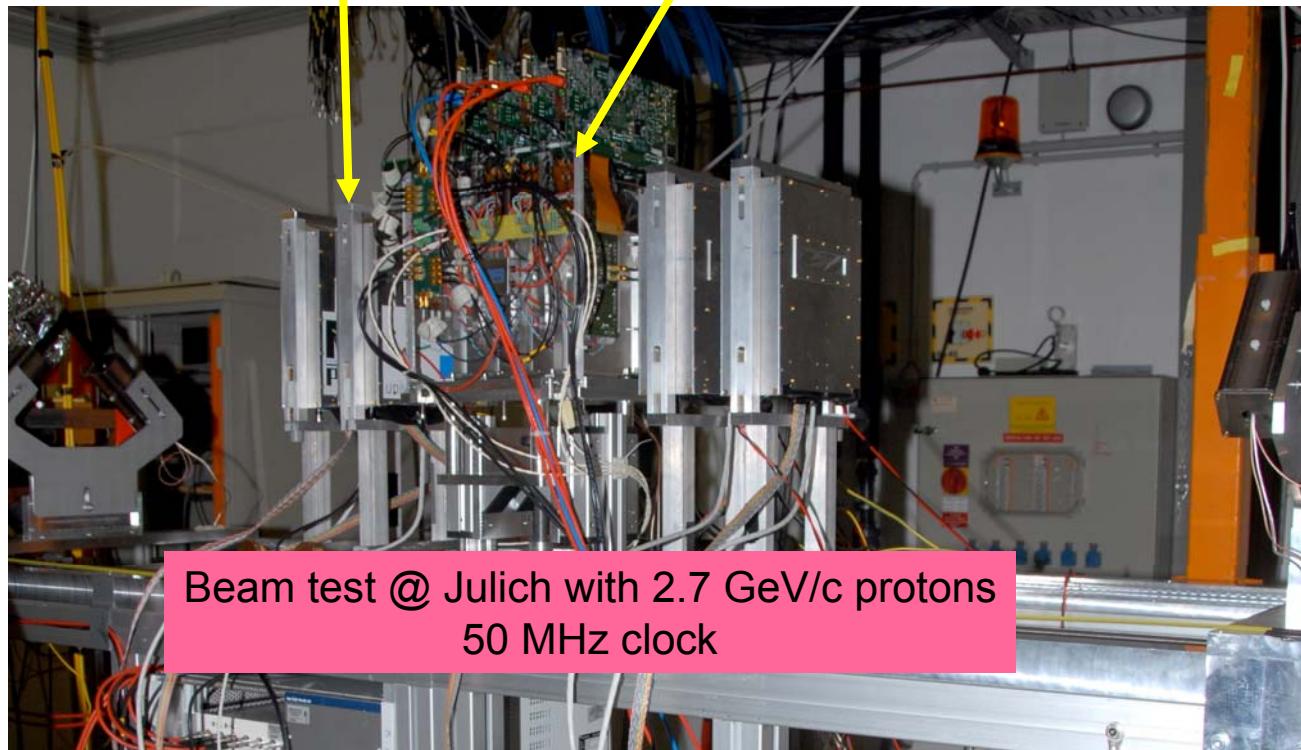
- Thickness 285 µm
 - 896 x 512 strips
 - 65 µm pitch
 - 90° stereo angle



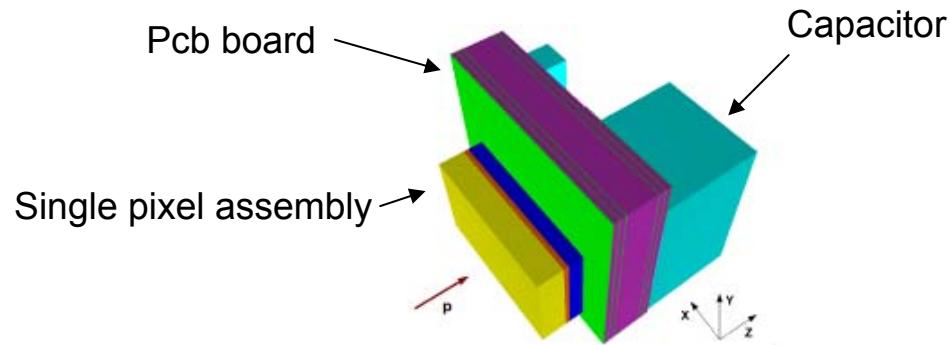
Tracking station



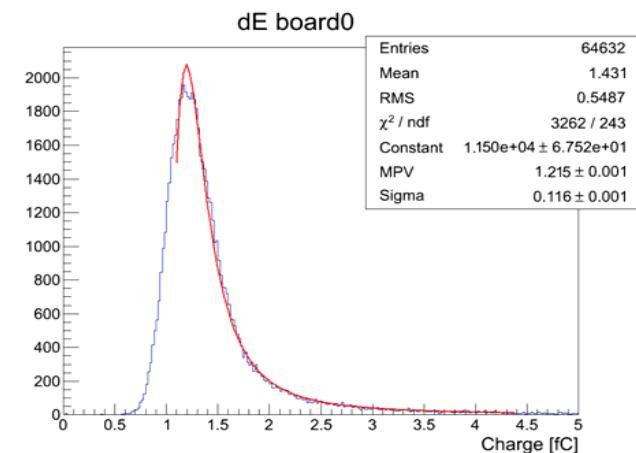
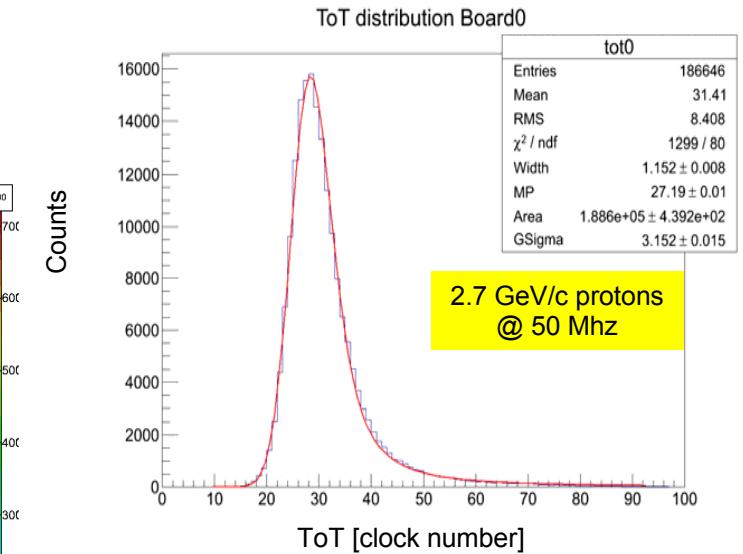
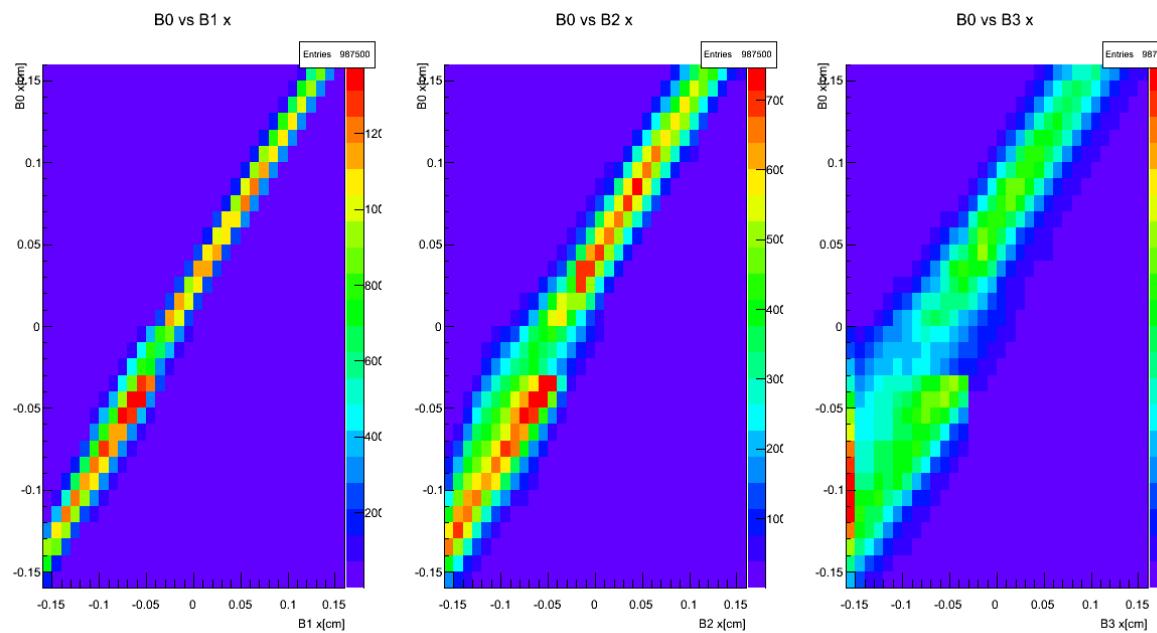
Pixel raw data:
Column & row
Timestamp
Leading &Trailing Edge
(Gray encoded)



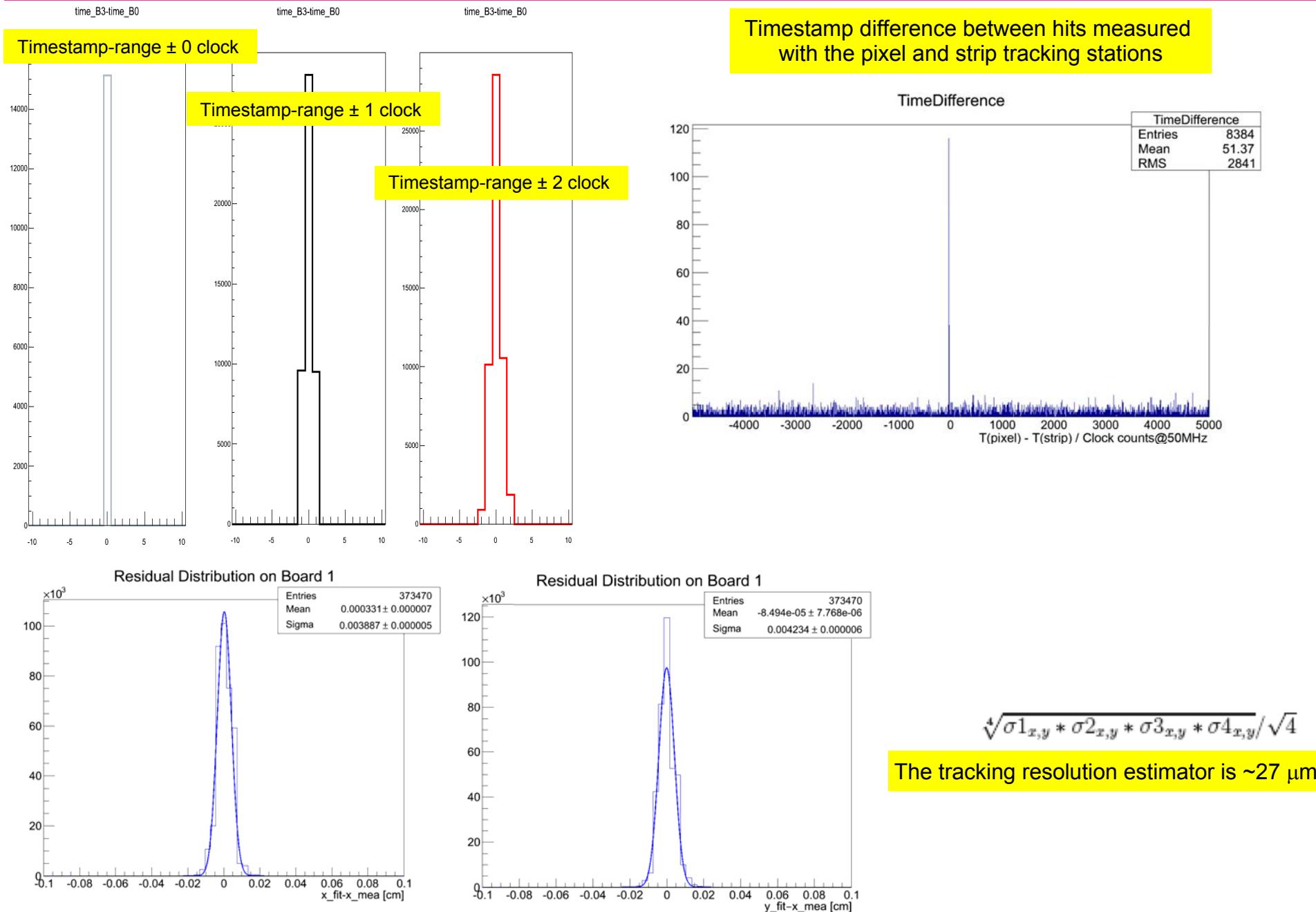
The material budget and ToT

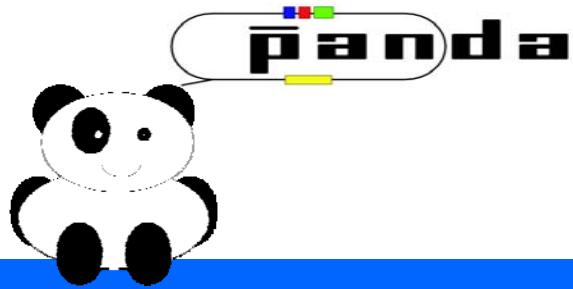


Number of planes	X/X_0	
	$x > 0$	$x < 0$
1 pixel	$\sim 5\%$	$\sim 6.6\%$
4 pixel	$\sim 20\%$	$\sim 26.6\%$
1 strip		$\sim 0.3\%$
4 strip		$\sim 1.3\%$
4 strip + 4 pixel	$\sim 21.38\%$	$\sim 27.91\%$



Timestamp selection and residuals





Conclusions

MVD Technical Design Report has been accepted by the PANDA collaboration and has been submitted to the FAIR committee

in December 2011

Tracking station with both triggerless pixel and triggered strips

Software development to check physics performance

and prototyping phase are ongoing

The PANDA Collaboration

More than 400 physicists from 55 institutions in 17 countries



U Basel
IHEP Beijing
U Bochum
U Bonn
U & INFN Brescia
U & INFN Catania
U Cracow
GSI Darmstadt
TU Dresden
JINR Dubna
 (LIT,LPP,VBLHE)
U Edinburgh
U Erlangen
NWU Evanston
U & INFN Ferrara
U Frankfurt
LNF-INFN Frascati

U & INFN Genova
U Glasgow
U Gießen
KVI Groningen
U Helsinki
IKP Jülich
U Katowice
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 Milano
U Minsk
TU München
U Münster
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